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TABLE OF CONTENTS

0: Modeling and Simulation Challenges in 3D Systems

Chairs: Yong Liu, *Fairchild Semiconductor*
Dan Oh, *Altera*

A Comparative Simulation Study of 3D Through Silicon Stack Assembly Processes	1
<i>Kamal Karimanal, Cielution LLC</i>	

Thermo Mechanical Challenges for Processing and Packaging Stacked Ultrathin Wafers	7
<i>Mario Gonzalez, IMEC; Bart Vandeveldel, IMEC; Antonio La Manna, IMEC; Bart Swinnen, IMEC; Eric Beyne, IMEC</i>	

Signal and Power Integrity Analysis of a 256-GB/s Double-Sided IC Package with a Memory Controller and 3D Stacked DRAM	13
<i>Wendemagegnehu Beyene, Rambus, Inc.; Hai Lan, Rambus, Inc.; Scott Best, Rambus, Inc.; David Secker, Rambus, Inc.; Don Mullen, Rambus, Inc.; Ming Li, Rambus, Inc.; Tom Giovannini, Rambus, Inc.</i>	

Optimization of 3D Stack for Electrical and Thermal Integrity	22
<i>Rishik Bazaz, Georgia Institute of Technology; Jianyong Xie, Georgia Institute of Technology; Madhavan Swaminathan, Georgia Institute of Technology</i>	

1: 3D Assembly and Reliability

Chairs: John Knickerbocker, *IBM Corporation*
Sam Karikalan, *Broadcom Corporation*

Reliability Studies on Micro-Bumps for 3-D TSV Integration	29
<i>Ho-Young Son, SK Hynix Inc.; Sung-Kwon Noh, SK Hynix Inc.; Hyun-Hee Jung, SK Hynix Inc.; Woong-Sun Lee, SK Hynix Inc.; Jae-Sung Oh, SK Hynix Inc.; Nam-Seog Kim, SK Hynix Inc.</i>	

Reliability Evaluation of a CoWoS-Enabled 3D IC Package	35
<i>Bahareh Banijamali, Xilinx, Inc.; Chien-Chia Chiu, Taiwan Semiconductor Manufacturing Company, Ltd.; Cheng-Chieh Hsieh, Taiwan Semiconductor Manufacturing Company, Ltd.; Tsung-Shu Lin, Taiwan Semiconductor Manufacturing Company, Ltd.; Clark Hu, Taiwan Semiconductor Manufacturing Company, Ltd.; Shang-Yun Hou, Taiwan Semiconductor Manufacturing Company, Ltd.; Suresh Ramalingam, Xilinx, Inc.; Shin-Puu Jeng, Taiwan Semiconductor Manufacturing Company, Ltd.; Liam Madden, Xilinx, Inc.; Doug C.H. Yu, Taiwan Semiconductor Manufacturing Company, Ltd.</i>	

TSV and Cu-Cu Direct Bond Wafer and Package-Level Reliability	41
<i>K. Hummler, SEMATECH; B. Sapp, SEMATECH; J.R. Lloyd, State University of New York, Albany; S. Kruger, SEMATECH, State University of New York, Albany; S. Olson, SEMATECH, State University of New York, Albany; S.B. Park, State University of New York, Binghamton; B. Murray, State University of New York, Binghamton; D. Jung, State University of New York, Binghamton; S. Cain, State University of New York, Binghamton; A. Park, State University of New York, Binghamton; D. Ferrone, State University of New York, Binghamton; I. Ali, SEMATECH</i>	

Generic Rules to Achieve Bump Electromigration Immortality for 3D IC Integration	49
<i>Hsiao-Yun Chen, Taiwan Semiconductor Manufacturing Company; Da-Yuan Shih, Taiwan Semiconductor Manufacturing Company; Cheng-Chang Wei, Taiwan Semiconductor Manufacturing Company; Chih-Hang Tung, Taiwan Semiconductor Manufacturing Company; Yi-Li Hsiao, Taiwan Semiconductor Manufacturing Company; Douglas Cheng-Hua Yu, Taiwan Semiconductor Manufacturing Company; Yu-Chun Liang, National Chiao Tung University; Chih Chen, National Chiao Tung University</i>	

3D Integration Technologies Using Self-Assembly and Electrostatic Temporary Multichip Bonding	58
T. Fukushima, <i>Tohoku University</i> ; H. Hashiguchi, <i>Tohoku University</i> ; J. Bea, <i>Tohoku University</i> ; M. Murugesan, <i>Tohoku University</i> ; K.-W. Lee, <i>Tohoku University</i> ; T. Tanaka, <i>Tohoku University</i> ; M. Koyanagi, <i>Tohoku University</i>	

Electrical Investigation and Reliability of 3D Integration Platform Using Cu TSVs and Micro-Bumps with Cu/Sn-BCB Hybrid Bonding	64
Yao-Jen Chang, <i>National Chiao Tung University</i> ; Cheng-Ta Ko, <i>National Chiao Tung University, Industrial Technology Research Institute (ITRI)</i> ; Zhi-Cheng Hsiao, <i>Industrial Technology Research Institute (ITRI)</i> ; Cheng-Hao Chiang, <i>National Chiao Tung University</i> ; Huan-Chun Fu, <i>Industrial Technology Research Institute (ITRI)</i> ; Tsung-Han Yu, <i>National Chiao Tung University</i> ; Cheng-Han Fan, <i>National Chiao Tung University</i> ; Wei-Chung Lo, <i>Industrial Technology Research Institute (ITRI)</i> ; Kuan-Neng Chen, <i>National Chiao Tung University</i>	

Assembly of 3D Chip Stack with 30µm-Pitch Micro Interconnects Using Novel Arrayed-Particles Anisotropic Conductive Film	71
Yu-Wei Huang, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Min Lin, <i>Industrial Technology Research Institute (ITRI)</i> ; Chau-Jie Zhan, <i>Industrial Technology Research Institute (ITRI)</i> ; Su-Tsai Lu, <i>Industrial Technology Research Institute (ITRI)</i> ; Shin-Yi Huang, <i>Industrial Technology Research Institute (ITRI)</i> ; Jing-Ye Juang, <i>Industrial Technology Research Institute (ITRI)</i> ; Chia-Wen Fan, <i>Industrial Technology Research Institute (ITRI)</i> ; Su-Ching Chung, <i>Industrial Technology Research Institute (ITRI)</i> ; Jon-Shiou Peng, <i>Industrial Technology Research Institute (ITRI)</i> ; Su-Mei Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Lan Lu, <i>Industrial Technology Research Institute (ITRI)</i> ; Pai-Cheng Chang, <i>Industrial Technology Research Institute (ITRI)</i> ; John H. Lau, <i>Industrial Technology Research Institute (ITRI)</i>	

2: 3D Materials and Processing
Chairs: Mikel Miller, *Draper Laboratory*
 Bing Dang, *IBM*

Development of 3D Through Silicon Stack (TSS) Assembly for Wide IO Memory to Logic Devices Integration	77
Dong Wook Kim, <i>Qualcomm Technologies, Inc.</i> ; Ramachandran Vidhya, <i>Qualcomm Technologies, Inc.</i> ; Brian Henderson, <i>Qualcomm Technologies, Inc.</i> ; Urmi Ray, <i>Qualcomm Technologies, Inc.</i> ; Sam Gu, <i>Qualcomm Technologies, Inc.</i> ; Wei Zhao, <i>Qualcomm Technologies, Inc.</i> ; Riko Radojicic, <i>Qualcomm Technologies, Inc.</i> ; Matt Nowak, <i>Qualcomm Technologies, Inc.</i> ; Changmin Lee, <i>Amkor Technology, Inc.</i> ; Jongsik Paek, <i>Amkor Technology, Inc.</i> ; Kiwook Lee, <i>Amkor Technology, Inc.</i> ; Ron Huemoeller, <i>Amkor Technology, Inc.</i>	

Investigation on the Properties and Processability of Polymeric Insulation Layers for Through Silicon Via	81
Songfang Zhao, <i>Chinese Academy of Sciences</i> ; Guoping Zhang, <i>Chinese Academy of Sciences</i> ; Chongnan Peng, <i>Chinese Academy of Sciences</i> ; Rong Sun, <i>Chinese Academy of Sciences</i> ; S.W. Ricky Lee, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Wenhui Zhu, <i>Kunshan Q Technology Ltd.</i> ; Fangqi Lai, <i>Kunshan Q Technology Ltd.</i>	

Process Integration of 3D Si Interposer with Double-Sided Active Chip Attachments	86
Pei-Jer Tzeng, <i>Industrial Technology Research Institute (ITRI)</i> ; John H. Lau, <i>Industrial Technology Research Institute (ITRI)</i> ; Chau-Jie Zhan, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Chen Hsin, <i>Industrial Technology Research Institute (ITRI)</i> ; Po-chih Chang, <i>Industrial Technology Research Institute (ITRI)</i> ; Yiu-Hsiang Chang, <i>Industrial Technology Research Institute (ITRI)</i> ; Jui-Chin Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Shang-Chun Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Chien-Ying Wu, <i>Industrial Technology Research Institute (ITRI)</i> ; Ching-Kuan Lee, <i>Industrial Technology Research Institute (ITRI)</i> ; Chun-Hsien Chien, <i>Industrial Technology Research Institute (ITRI)</i> ; Hsiang-Hung Chang, <i>Industrial Technology Research Institute (ITRI)</i> ; Cha-Hsin Lin, <i>Industrial Technology Research Institute (ITRI)</i> ; Tzu-Kun Ku, <i>Industrial Technology Research Institute (ITRI)</i> ; Ming-Jer Kao, <i>Industrial Technology Research Institute (ITRI)</i> ; Ming Li, <i>Rambus Inc.</i> ; Julia Cline, <i>Rambus Inc.</i> ; Keisuke Saito, <i>Rambus Inc.</i> ; Mandy Ji, <i>Rambus Inc.</i>	

Analyzing the Behavior and Shear Strength of Common Adhesives Used in Temporary Wafer Bonding	94
J.A. Sharpe, <i>University of Alabama</i> ; M.B. Jordan, <i>University of Alabama</i> ; S.L. Burkett, <i>University of Alabama</i> ; M.E. Barkey, <i>University of Alabama</i>	
WSS and ZoneBOND Temporary Bonding Techniques Comparison for 80µm and 55µm Functional Interposer Creation	101
A. Jouve, <i>CEA-LETI</i> ; K. Vial, <i>CEA-LETI</i> ; E. Rolland, <i>CEA-LETI</i> ; P. Coudrain, <i>STMicroelectronics</i> ; C. Aumont, <i>STMicroelectronics</i> ; C. Laviron, <i>CEA-LETI</i> ; F. Fournel, <i>CEA-LETI</i> ; M. Pellat, <i>CEA-LETI</i> ; P. Montmeat, <i>CEA-LETI</i> ; N. Allouti, <i>CEA-LETI</i> ; R. Eleouet, <i>CEA-LETI</i> ; M. Argoud, <i>CEA-LETI</i> ; J. Dechamp, <i>CEA-LETI</i> ; L. Bally, <i>CEA-LETI</i> ; L. Vignoud, <i>CEA-LETI</i> ; C. Donche, <i>CEA-LETI</i> ; R. Hida, <i>CEA-LETI</i> ; C. Ratin, <i>CEA-LETI</i> ; T. Magis, <i>CEA-LETI</i> ; V. Loup, <i>CEA-LETI</i> ; R. Kachtouli, <i>CEA-LETI</i> ; L. Gabette, <i>CEA-LETI</i> ; T. Mourier, <i>CEA-LETI</i> ; S. Cheramy, <i>CEA-LETI</i> ; N. Sillon, <i>CEA-LETI</i>	
Low Cost, Room Temperature Debondable Spin-On Temporary Bonding Solution: A Key Enabler for 2.5D/3D IC Packaging	107
Ranjith Samuel E. John, <i>Dow Corning Corporation</i> ; Herman Meynen, <i>Dow Corning Corporation</i> ; Sheng Wang, <i>Dow Corning Corporation</i> ; Peng-Fei Fu, <i>Dow Corning Corporation</i> ; Craig Yeakle, <i>Dow Corning Corporation</i> ; Sang Wook W. Kim, <i>Dow Corning Corporation</i> ; Lyndon J. Larson, <i>Dow Corning Corporation</i> ; Scott Sullivan, <i>Suss MicroTec</i>	
Integration and Manufacturing Aspects of Moving from WaferBOND HT-10.10 to ZoneBOND Material in Temporary Wafer Bonding and Debonding for 3D Applications	113
Anne Jourdain, <i>IMEC</i> ; Alain Phommahaxay, <i>IMEC</i> ; Greet Verbinnen, <i>IMEC</i> ; Gayle Murdoch, <i>IMEC</i> ; Andy Miller, <i>IMEC</i> ; Kenneth Rebibis, <i>IMEC</i> ; Alice Guerrero, <i>Brewer Science, Inc.</i> ; Jeremy McCutcheon, <i>Brewer Science, Inc.</i> ; Mark Privett, <i>Brewer Science, Inc.</i> ; Jason Neidrich, <i>Brewer Science, Inc.</i> ; Gerald Beyer, <i>IMEC</i> ; Eric Beyne, <i>IMEC</i>	
3: Novel Interconnections	
Chairs:	James E. Morris, <i>Portland State University</i> Lei Shan, <i>IBM Corporation</i>
Effects of Nanofiber Materials of Nanofiber Anisotropic Conductive Adhesives (Nanofiber ACAs) for Ultra-Fine Pitch Electronic Assemblies	118
Kyoung-Lim Suk, <i>KAIST</i> ; Kyung-Wook Paik, <i>KAIST</i>	
A Novel Non-TSV Approach to Enhancing the Bandwidth in 3-D Packages for Processor-Memory Modules	124
D. Gupta, <i>APSTL LLC</i>	
Three-Path Electroplated Copper Compliant Interconnects – Fabrication and Modeling Studies	129
Raphael Okereke, <i>Georgia Institute of Technology</i> ; Suresh K. Sitaraman, <i>Georgia Institute of Technology</i>	
Ultra-Fine Trench Circuit on Polymer Film	136
Takaharu Hondo, <i>Fujikura, Ltd.</i> ; Yosuke Nitta, <i>Fujikura, Ltd.</i> ; Kei Nakamura, <i>Fujikura, Ltd.</i> ; Hiroyuki Hirano, <i>Fujikura, Ltd.</i> ; Masanobu Saruta, <i>Fujikura, Ltd.</i> ; Toshiaki Inoue, <i>Fujikura, Ltd.</i> ; Osamu Nakao, <i>Fujikura, Ltd.</i>	
A Highly Integratable Millimeter-Wave Silicon Waveguide Array for Terabit Application	140
Qidong Wang, <i>Chinese Academy of Sciences</i> ; Daniel Guidotti, <i>Chinese Academy of Sciences</i> ; Jie Cui, <i>Chinese Academy of Sciences</i> ; Liqiang Cao, <i>Chinese Academy of Sciences</i> ; Tianchun Ye, <i>Chinese Academy of Sciences</i> ; Lixi Wan, <i>Chinese Academy of Sciences</i>	
Aluminum to Aluminum Bonding at Room Temperature	146
F. Marion, <i>CEA-LETI</i> ; B. Goubault de Brugière, <i>CEA-LETI</i> ; A. Bedoin, <i>CEA-LETI</i> ; M. Volpert, <i>CEA-LETI</i> ; F. Berger, <i>CEA-LETI</i> ; A. Gueugnot, <i>CEA-LETI</i> ; R. Anciant, <i>CEA-LETI</i> ; H. Ribot, <i>CEA-LETI</i>	

Carbon Nanotube Array as High Impedance Interconnects for Sensing Device Integration	154
Dunlin Tan, <i>Thales Solutions Asia Pte Ltd, CINTRA, Nanyang Technological University</i> ; Chin Chong Yap, <i>CINTRA, Nanyang Technological University</i> ; David Hee, <i>Thales Solutions Asia Pte Ltd</i> ; JongJen Yu, <i>Thales Solutions Asia Pte Ltd</i> ; Jean-Luc Reverchon, <i>Thales Solutions Asia Pte Ltd</i> ; Philippe Bois, <i>Thales Solutions Asia Pte Ltd</i> ; Dominique Baillargeat, <i>CINTRA</i> ; Beng Kang Tay, <i>Nanyang Technological University</i>	
4: Reliability Test Methods	
Chairs: John H.L. Pang, <i>Nanyang Technological University</i> Deepak Goyal, <i>Intel Corporation</i>	
Define Electrical Packing Temperature Cycling Requirement with Field Measured User Behavior Data	159
Min Pei, <i>Intel Corporation</i> ; Ru Han, <i>Intel Corporation</i> ; Daeil Kwon, <i>Intel Corporation</i> ; Alan Lucero, <i>Intel Corporation</i> ; Vasu Vasudevan, <i>Intel Corporation</i> ; Robert Kwasnick, <i>Intel Corporation</i> ; Praveen S. Polasam, <i>Intel Corporation</i>	
Characterization of Aging Effects in Lead Free Solder Joints Using Nanoindentation	166
Mohammad Hasnine, <i>Auburn University</i> ; Muhannad Mustafa, <i>Auburn University</i> ; Jeffrey C. Suhling, <i>Auburn University</i> ; Barton C. Prorok, <i>Auburn University</i> ; Michael J. Bozack, <i>Auburn University</i> ; Pradeep Lall, <i>Auburn University</i>	
Effects of Reliability Testing Methods on Microstructure and Strength at the Cu Wire-AI Pad Interface	179
Peng Su, <i>Cisco Systems, Inc.</i> ; Hidetoshi Seki, <i>Sumitomo Bakelite Company, Ltd.</i> ; Chen Ping, <i>Sumitomo Bakelite Singapore Pte. Ltd.</i> ; Shingo Itoh, <i>Sumitomo Bakelite Company, Ltd.</i> ; Louie Huang, <i>Advanced Semiconductor Engineering, Inc.</i> ; Nicholas Liao, <i>Advanced Semiconductor Engineering, Inc.</i> ; Bill Liu, <i>Advanced Semiconductor Engineering, Inc.</i> ; Curtis Chen, <i>Advanced Semiconductor Engineering, Inc.</i> ; Winnie Tai, <i>Advanced Semiconductor Engineering, Inc.</i> ; Andy Tseng, <i>Advanced Semiconductor Engineering, Inc.</i>	
Use of RF-Based Technique as a Metrology Tool for TSV Reliability Analysis	186
Chukwudi Okoro, <i>NIST</i> ; Pavel Kabos, <i>NIST</i> ; Jan Obrzut, <i>NIST</i> ; Klaus Hummler, <i>SEMATECH</i> ; Yaw S. Obeng, <i>NIST</i>	
On the Use of High Precision Electrical Resistance Measurement for Analyzing the Damage Development During Accelerated Test of Pb-Free Solder Interconnects	192
J. Zhang, <i>Materials Innovation Institute, Delft University of Technology</i> ; S. van der Zwaag, <i>Delft University of Technology</i> ; H.W. Zeijl, <i>Delft University of Technology</i> ; G.Q. Zhang, <i>Delft University of Technology, Philips Lighting</i>	
Unique Adhesion Testing and MSL Modeling	200
Masazumi Amagai, <i>Texas Instruments</i> ; Kentaro Takao, <i>Texas Instruments</i>	
Acoustic Emission Detection of BGA Components in Spherical Bend	208
W. Carter Ralph, <i>Southern Research Institute</i> ; Gregory L. Daspit, <i>Southern Research Institute</i> ; Andrew W. Cain, <i>Southern Research Institute</i> ; Elizabeth F. Benedetto, <i>Hewlett-Packard</i> ; Randall S. Jenkins, <i>Southern Research Institute</i> ; Aileen M. Allen, <i>Hewlett-Packard</i> ; Keith Newman, <i>Hewlett-Packard</i>	
5: New Directions in Packaging	
Chairs: Vasudeva P. Atluri, <i>Renavitas Technologies</i> Joana Maria, <i>IBM Watson Research</i>	
Large-Scale, Surface Tension Assisted Ball-in-Pit Self Population for Chip-to-Chip Passive Alignment	214
Chaoqi Zhang, <i>Georgia Institute of Technology</i> ; Hiren D. Thacker, <i>Oracle Labs</i> ; Ivan Shubin, <i>Oracle Labs</i> ; Ashok V. Krishnamoorthy, <i>Oracle Labs</i> ; James G. Mitchell, <i>Oracle Labs</i> ; John E. Cunningham, <i>Oracle Labs</i>	

Through-Silicon-Via Process Control in Manufacturing for SiGe Power Amplifiers	221
J.P. Gambino, <i>IBM Microelectronics</i> ; T. Doan, <i>IBM Microelectronics</i> ; J. Trapasso, <i>IBM Microelectronics</i> ; C. Musante, <i>IBM Microelectronics</i> ; D. Dang, <i>IBM Microelectronics</i> ; D. Vanslette, <i>IBM Microelectronics</i> ; D. Grant, <i>Tamar Technology</i> ; D. Marx, <i>Tamar Technology</i> ; R. Dudley, <i>Tamar Technology</i>	
High Frequency Scanning Acoustic Microscopy Applied to 3D Integrated Process: Void Detection in Through Silicon Vias	227
Alain Phommahaxay, <i>IMEC</i> ; Ingrid De Wolf, <i>IMEC, KU Leuven</i> ; Peter Hoffrogge, <i>PVA TePla Analytical Systems GmbH</i> ; Sebastian Brand, <i>PVA TePla Analytical Systems GmbH</i> ; Peter Czurratis, <i>PVA TePla Analytical Systems GmbH</i> ; Harold Philipsen, <i>IMEC</i> ; Yann Civale, <i>IMEC</i> ; Kevin Vandersmissen, <i>IMEC</i> ; Sandip Halder, <i>IMEC</i> ; Gerald Beyer, <i>IMEC</i> ; Bart Swinnen, <i>IMEC</i> ; Andy Miller, <i>IMEC</i> ; Eric Beyne, <i>IMEC</i>	
Self-Alignment Structures for Heterogeneous 3D Integration	232
Hyung Suk Yang, <i>Georgia Institute of Technology</i> ; Chaoqi Zhang, <i>Georgia Institute of Technology</i> ; Muhannad S. Bakir, <i>Georgia Institute of Technology</i>	
Optimization of Wire-Rod Electrostatic Fluid Accelerators	240
Tsrong-Yi Wen, <i>University of Washington</i> ; Tsan-Ting Shen, <i>University of Washington</i> ; Hsiu-Che Wang, <i>University of Washington</i> ; Alexander Mamishev, <i>University of Washington</i>	
New Selective Wet Processing	247
M. Balucani, <i>University of Rome, Rise Technology</i> ; D. Ciarniello, <i>Rise Technology</i> ; P. Nenzi, <i>University of Rome</i> ; D. Bernardi, <i>2BG</i> ; R. Crescenzi, <i>University of Rome</i> ; K. Kholostov, <i>University of Rome</i>	
Microscrubbing: An Alternative Method for 3D Thermocompression Bonding CuCu Bumps and High Bump Density Devices with Low Force, Time, and Temperature	255
Robert Daily, <i>IMEC</i> ; Wang Teng, <i>IMEC</i> ; Giovanni Capuz, <i>IMEC</i> ; Andy Miller, <i>IMEC</i>	
6: Optical Interconnects	
Chairs:	Alex Rosiewicz, <i>Gooch & Housego</i> Ping Zhou, <i>LDX Optronics, Inc.</i>
Optical Backplane for Board-to-Board Interconnection Based on a Glass Panel Gradient-Index Multimode Waveguide Technology	260
Lars Brusberg, <i>Fraunhofer IZM</i> ; Henning Schröder, <i>Fraunhofer IZM</i> ; Richard Pitwon, <i>Xyratex Technology Ltd.</i> ; Simon Whalley, <i>ILFA Feinstleitertechnik GmbH</i> ; Christian Herbst, <i>Technical University Berlin</i> ; Allen Miller, <i>Xyratex Technology Ltd.</i> ; Marcel Neitz, <i>Technical University Berlin</i> ; Julia Röder, <i>Fraunhofer IZM</i> ; Klaus-Dieter Lang, <i>Technical University Berlin</i>	
Single-Chip 4 TX + 4 RX Optical Module Based on Holey SiGe Transceiver IC	268
Fuad E. Doany, <i>IBM T.J. Watson Research Center</i> ; Daniel M. Kuchta, <i>IBM T.J. Watson Research Center</i> ; Alexander V. Rilyakov, <i>IBM T.J. Watson Research Center</i> ; Christian W. Baks, <i>IBM T.J. Watson Research Center</i> ; Frank Libsch, <i>IBM T.J. Watson Research Center</i> ; Clint L. Schow, <i>IBM T.J. Watson Research Center</i>	
FPC-Based Compact 25-Gb/s Optical Transceiver Module for Optical Interconnect Utilizing Novel High-Speed FPC Connector	274
Takatoshi Yagisawa, <i>Fujitsu Laboratories Ltd.</i> ; Takashi Shiraishi, <i>Fujitsu Laboratories Ltd.</i> ; Tadashi Ikeuchi, <i>Fujitsu Laboratories Ltd.</i> ; Kazuhiro Tanaka, <i>Fujitsu Laboratories Ltd.</i>	
Optical Packaging of Silicon Photonic Devices for External Connection of Parallel Optical Signals	280
Yoichi Taira, <i>IBM Research - Tokyo</i> ; Hidetoshi Numata, <i>IBM Research - Tokyo</i>	
Modeling, Design, and Fabrication of Ultra-High Bandwidth 3D Glass Photonics (3DGP) in Glass Interposers	286
Bruce C. Chou, <i>Georgia Institute of Technology</i> ; Yoichiro Sato, <i>Asahi Glass Company</i> ; Vijay Sukumaran, <i>Georgia Institute of Technology</i> ; Jibin Sun, <i>TE Connectivity</i> ; Venky Sundaram, <i>Georgia Institute of Technology</i> ; Gee-Kung Chang, <i>Georgia Institute of Technology</i> ; Rao Tummala, <i>Georgia Institute of Technology</i>	

Assembly Development of 1.3 Tb/s Full Duplex Optical Module	292
Yehoshua Benjamin, <i>Compass Electro Optical Systems</i> ; Kobi Hasharoni, <i>Compass Electro Optical Systems</i> ; Michael Mesh, <i>Compass Electro Optical Systems</i>	
Low-Loss Design and Fabrication of Multimode Polymer Optical Waveguide Circuit with Crossings for High-Density Optical PCB	297
Takaaki Ishigure, <i>Keio University</i> ; Keishiro Shitanda, <i>Keio University</i> ; Takuya Kudo, <i>Keio University</i> ; Shotaro Takayama, <i>Sumitomo Bakelite Co., Ltd.</i> ; Tetsuya Mori, <i>Sumitomo Bakelite Co., Ltd.</i> ; Kimio Moriya, <i>Sumitomo Bakelite Co., Ltd.</i> ; Koji Choki, <i>Sumitomo Bakelite Co., Ltd.</i>	
7: Interposers	
Chairs:	Subhash L. Shinde, <i>Sandia National Laboratory</i> Peter Ramm, <i>Fraunhofer EMFT</i>
Full Integration of a 3D Demonstrator with TSV First Interposer, Ultra Thin Die Stacking, and Wafer Level Packaging	305
G. Parès, <i>CEA-LETI</i> ; C. Karoui, <i>STMicroelectronics</i> ; A. Zaid, <i>STMicroelectronics</i> ; F. Dosseul, <i>STMicroelectronics</i> ; M. Feron, <i>STMicroelectronics</i> ; A. Attard, <i>BESI Austria GmbH</i> ; G. Klug, <i>DISCO Hi-Tec Europe GmbH</i> ; H. Luesebrink, <i>PVA TePla AG</i> ; K. Martinschitz, <i>E. Thallner GmbH</i> ; N. Launay, <i>SPTS</i> ; S. Belhenini, <i>LMR</i> ; G. Simon, <i>CEA-LETI</i>	
Fabrication and Testing of Thin Silicon Interposers with Multilevel Frontside and Backside Metallization and Cu-Filled TSVs	317
M. Lueck, <i>RTI International</i> ; D. Malta, <i>RTI International</i> ; A. Huffman, <i>RTI International</i> ; C. Gregory, <i>RTI International</i> ; M. Butler, <i>RTI International</i> ; J. Lannon, <i>RTI International</i> ; D.S. Temple, <i>RTI International</i>	
Interposer Technology for High Bandwidth Interconnect Applications	323
Mikael Detalle, <i>IMEC</i> ; A. La Manna, <i>IMEC</i> ; J. De Vos, <i>IMEC</i> ; P. Nolmans, <i>IMEC</i> ; R. Daily, <i>IMEC</i> ; Y. Civale, <i>IMEC</i> ; G. Beyrer, <i>IMEC</i> ; E. Beyrer, <i>IMEC</i>	
Package Demonstration of an Interposer with Integrated TSVs and Flexible Compliant Interconnects	329
I. Shubin, <i>Oracle</i> ; E.M. Chow, <i>Palo Alto Research Center (PARC)</i> ; A. Chow, <i>Oracle</i> ; D. De Bruyker, <i>Palo Alto Research Center (PARC)</i> ; H.D. Thacker, <i>Oracle</i> ; K. Fujimoto, <i>DNP America, LLC</i> ; K. Raj, <i>Oracle</i> ; A.V. Krishnamoorthy, <i>Oracle</i> ; J.G. Mitchell, <i>Oracle</i> ; J.E. Cunningham, <i>Oracle</i>	
Electrical and Morphological Characterization for High Integrated Silicon Interposer and Technology Transfer from 200mm to 300mm Wafer	334
Masahiro Sunohara, <i>Shinko Electric Industries Co., Ltd.</i> ; Ken Miyairi, <i>Shinko Electric Industries Co., Ltd.</i> ; Kenichi Mori, <i>Shinko Electric Industries Co., Ltd.</i> ; Kei Murayama, <i>Shinko Electric Industries Co., Ltd.</i> ; Jean Charbonnier, <i>CEA-LETI</i> ; Myriam Assous, <i>CEA-LETI</i> ; Jean-Philippe Bally, <i>CEA-LETI</i> ; Thierry Mourier, <i>CEA-LETI</i> ; Stephane Minoret, <i>CEA-LETI</i> ; Denis Mercier, <i>CEA-LETI</i> ; Alain Toffoli, <i>CEA-LETI</i> ; Fabieene Allain, <i>CEA-LETI</i> ; Eugénie Martinez, <i>CEA-LETI</i> ; Hélène Feldis, <i>CEA-LETI</i> ; Gilles Simon, <i>CEA-LETI</i> ; Mitsutoshi Higashi, <i>CEA-LETI</i>	
Low Cost, High Performance, and High Reliability 2.5D Silicon Interposer	342
Venky Sundaram, <i>Georgia Institute of Technology</i> ; Qiao Chen, <i>Georgia Institute of Technology</i> ; Tao Wang, <i>Georgia Institute of Technology</i> ; Hao Lu, <i>Georgia Institute of Technology</i> ; Yuya Suzuki, <i>Zeon Corporation</i> ; Vanessa Smet, <i>Georgia Institute of Technology</i> ; Makoto Kobayashi, <i>Namics Corporation</i> ; Raj Pulugurtha, <i>Georgia Institute of Technology</i> ; Rao Tummala, <i>Georgia Institute of Technology</i>	
Development of Through Glass Via (TGV) Formation Technology Using Electrical Discharging for 2.5D/3D Integrated Packaging	348
Shintaro Takahashi, <i>Asahi Glass Company, Ltd.</i> ; Kohei Horiuchi, <i>Asahi Glass Company, Ltd.</i> ; Kentaro Tatsukoshi, <i>Asahi Glass Company, Ltd.</i> ; Motoshi Ono, <i>Asahi Glass Company, Ltd.</i> ; Nobuhiko Imajo, <i>Asahi Glass Company, Ltd.</i> ; Tim Mobely, <i>nMode Solutions, Inc.</i>	

8: 3D Reliability and Packaging Challenges

Chairs: Toni Mattila, *Aalto University*
Jeffrey Suhling, *Auburn University*

Thermomechanical and Electrochemical Reliability of Fine-Pitch Through-Package-Copper Vias (TPV) in Thin Glass Interposers and Packages 353

Kaya Demir, *Georgia Institute of Technology*; Koushik Ramachandran, *Georgia Institute of Technology*; Yoichiro Sato, *Asahi Glass Co., Ltd.*; Qiao Chen, *Georgia Institute of Technology*; Vijay Sukumaran, *Georgia Institute of Technology*; Raghu Pucha, *Georgia Institute of Technology*; Venkatesh Sundaram, *Georgia Institute of Technology*; Rao Tummala, *Georgia Institute of Technology*

Impacts of Static and Dynamic Local Bending of Thinned Si Chip on MOSFET Performance in 3-D Stacked LSI 360

H. Kino, *Tohoku University*; J.-C. Bea, *Tohoku University*; M. Murugesan, *Tohoku University*; K.-W. Lee, *Tohoku University*; T. Fukushima, *Tohoku University*; M. Koyanagi, *Tohoku University*; T. Tanaka, *Tohoku University*

Reliability Characterization of Chip-on-Wafer-on-Substrate (CoWoS) 3D IC Integration Technology 366

Larry Lin, *Taiwan Semiconductor Manufacturing Company, Ltd.*; Tung-Chin Yeh, *Taiwan Semiconductor Manufacturing Company, Ltd.*; Jyun-Lin Wu, *Taiwan Semiconductor Manufacturing Company, Ltd.*; Gary Lu, *Taiwan Semiconductor Manufacturing Company, Ltd.*; Tsung-Fu Tsai, *Taiwan Semiconductor Manufacturing Company, Ltd.*; Larry Chen, *Taiwan Semiconductor Manufacturing Company, Ltd.*; An-Tai Xu, *Taiwan Semiconductor Manufacturing Company, Ltd.*

Accelerated Reliability Testing and Modeling of Cu-Plated Through Encapsulant Vias (TEVs) for 3D-Integration 372

B. Wunderle, *Technical University Chemnitz*; J. Heilmann, *Technical University Chemnitz*; S.G. Kumar, *Technical University Chemnitz*; O. Hoelck, *Technical University Chemnitz, Fraunhofer IZM*; H. Walter, *Fraunhofer IZM*; O. Wittler, *Fraunhofer IZM*; G. Engelmann, *Fraunhofer IZM*; M.J. Wolf, *Fraunhofer IZM*; G. Beer, *Infineon Technologies AG*; K. Pressel, *Infineon Technologies AG*

Reliability Study for Large Silicon Interposers Report on Board 383

C. Ferrandon, *CEA-LETI*; S. Joblot, *STMicroelectronics*; Y. Lamy, *CEA-LETI*; P. Coudrain, *STMicroelectronics*; P. Bar, *STMicroelectronics*; D. Yap, *STMicroelectronics*; F. De Crecy, *CEA-LETI*; R. Coffy, *STMicroelectronics*; J.-F. Carpentier, *STMicroelectronics*; G. Simon, *CEA-LETI*

Fracture Mechanics Life-time Modeling of Low Temperature Si Fusion Bonded Interfaces Used for 3D MEMS Device Integration 390

Falk Naumann, *Fraunhofer IWM*; Michael Bernasch, *Fraunhofer IWM*; Joerg Siegert, *ams AG*; Sara Camiello, *ams AG*; Matthias Petzold, *Fraunhofer IWM*

Extension of Micro-Raman Spectroscopy for Full-Component Stress Characterization of TSV Structures 397

Qiu Zhao, *University of Texas, Austin*; J. Im, *University of Texas, Austin*; R. Huang, *University of Texas, Austin*; P.S. Ho, *University of Texas, Austin*

9: Advanced Flip Chip Technologies

Chairs: Lou Nicholls, *Amkor Technology, Inc.*
William Chen, *Advanced Semiconductor Engineering, Inc.*

Challenges of Chip-to-Package Interaction for 22nm Technology with Ultra Low k and Pb-Free Interconnects 402

Chris Muzzy, *IBM Corporation*; Richard Bisson, *IBM Corporation*; John Cincotta, *IBM Corporation*; Danielle Degraw, *IBM Corporation*; Edward Engbrecht, *IBM Corporation*; Jason Gill, *IBM Corporation*; Naftali Lustig, *IBM Corporation*; Karen McLaughlin, *IBM Corporation*; Sylvain Ouimet, *IBM Corporation*; Joseph Ross, *IBM Corporation*; David Turnbull, *IBM Corporation*

Ultra-Thin and Ultra-High I/O Density Package-on-Package (3D Thin PoP) for High Bandwidth of Smart Systems	406
Sung Jin Kim, <i>Georgia Institute of Technology</i> ; Chinmay Honrao, <i>Georgia Institute of Technology</i> ; P. Markondeya Raj, <i>Georgia Institute of Technology</i> ; Venky Sundaram, <i>Georgia Institute of Technology</i> ; Rao Tummala, <i>Georgia Institute of Technology</i>	
A PoP Structure to Support I/O over 1000	412
Dyi-Chung Hu, <i>Unimicron Technology Corporation</i> ; Chun-Ting Lin, <i>Unimicron Technology Corporation</i> ; Ying-Chih Chan, <i>Unimicron Technology Corporation</i>	
Investigation of Novel Solder Patterns for Power Delivery and Heat Removal Support	417
Thomas Brunschwiler, <i>IBM Research – Zurich</i> ; Yassir Madhour, <i>IBM Research – Zurich, Swiss Institute of Technology</i> ; Timo Tick, <i>IBM Research – Zurich</i> ; Gerd Schlottig, <i>IBM Research – Zurich</i> ; Stefano Oggioni, <i>IBM ISC Eng.</i>	
Modified Thermosonic Flip-Chip Bonding Based on Electroplated Cu Microbumps and Concave Pads for High-Precision Low-Temperature Assembly Applications	425
Tung Thanh Bui, <i>AIST</i> ; Motohiro Suzuki, <i>AIST</i> ; Fumiki Kato, <i>AIST</i> ; Naoya Watanabe, <i>AIST</i> ; Shunsuke Nemoto, <i>AIST</i> ; Katsuya Kikuchi, <i>AIST</i> ; Masahiro Aoyagi, <i>AIST</i>	
10µm Ag Flip-Chip by Solid-State Bonding at 250°C	431
Wen P. Lin, <i>University of California, Irvine</i> ; Chin C. Lee, <i>University of California, Irvine</i>	
Transient Liquid Phase Sintered Attach for Power Electronics	435
Hannes Greve, <i>University of Maryland</i> ; Liang-Yu Chen, <i>Ohio Aerospace Institute</i> ; Ian Fox, <i>Aero Engine Controls</i> ; F. Patrick McCluskey, <i>University of Maryland</i>	
10: Advancements in Manufacturing Technology	
Chairs:	Shawn Shi, <i>Medtronic Corporation</i> Sharad Bhatt, <i>Shanta Systems, Inc.</i>
Strip Warpage Analysis of a Flip Chip Package Considering the Mold Compound Processing Parameters	441
MyoungSu Chae, <i>STATS ChipPAC, Ltd.</i> ; Eric Ouyang, <i>STATS ChipPAC, Ltd.</i>	
Thermoplastic Based System-in-Package for RFID Application	449
Christine Kallmayer, <i>Fraunhofer IZM</i> ; Barbara Pahl, <i>Fraunhofer IZM</i> ; Arian Grams, <i>Fraunhofer IZM</i> ; Joao Marques, <i>Technical University Berlin</i> ; Klaus-Dieter Lang, <i>Technical University Berlin</i> ; Thomas Suwald, <i>NXP Semiconductors</i>	
3D Printing of Structures with Embedded Circuit Boards Using Novel Holographic Optics	455
Shuai Hou, <i>Loughborough University</i> ; John Tyrer, <i>Loughborough University</i>	
Low Temperature Fine Pitch Flex-on-Flex (FOF) Assembly Using Nanofiber Sn58Bi Solder Anisotropic Conductive Films (ACFs) and Ultrasonic Bonding Method	461
Tae Wan Kim, <i>KAIST</i> ; Kyoung-Lim Suk, <i>KAIST</i> ; Kyung-Wook Paik, <i>KAIST</i>	
Effective Voiding Control of QFN Via Solder Mask Patterning	468
Derrick Herron, <i>Indium Corporation</i> ; Yan Liu, <i>Indium Corporation</i> ; Ning-Cheng Lee, <i>Indium Corporation</i>	
Warpage Analysis and Improvement for a Power Module	475
Yong Liu, <i>Fairchild Semiconductor Corporation</i> ; Yumin Liu, <i>Fairchild Semiconductor Corporation</i> ; Zhongfa Yuan, <i>Fairchild Semiconductor Corporation</i> ; Tyler Chen, <i>Fairchild Semiconductor Corporation</i> ; Keunhyuk Lee, <i>Fairchild Semiconductor Corporation</i> ; Suresh Belani, <i>Fairchild Semiconductor Corporation</i>	

Solder Joint Properties of Sn-Ag-Cu Solders on Environmental-Friendly Plasma Surface Finish	481
Sang-Hyun Kwon, <i>Korea Institute of Industrial Technology (KITECH)</i> ; Kyoung-Ho Kim, <i>Korea Institute of Industrial Technology (KITECH)</i> ; Won-Il Seo, <i>Korea Institute of Industrial Technology (KITECH)</i> ; Nam-Sun Park, <i>Jesagi Hankook Ltd.</i> ; Young-Bae Park, <i>Andong National University</i> ; Chang-Woo Lee, <i>Korea Institute of Industrial Technology (KITECH)</i> ; Sehoon Yoo, <i>Korea Institute of Industrial Technology (KITECH)</i>	
11: Biomedical Electronics	
Chairs:	C.S. Premachandran, <i>GLOBALFOUNDRIES</i> Karlheinz Bock, <i>Fraunhofer EMFT</i>
Smart Flexible Planar Electrodes for Electrochemotherapy and Biosensing	486
Paolo Nenzi, <i>University of Rome</i> ; Agnese Denzi, <i>University of Rome</i> ; Konstantin Kholostov, <i>University of Rome</i> ; Rocco Crescenzi, <i>University of Rome</i> ; Francesca Apollonio, <i>University of Rome</i> ; Micaela Liberti, <i>University of Rome</i> ; Paolo Marracino, <i>University of Rome</i> ; Alessia Ongaro, <i>University of Ferrara</i> ; Ruggero Cadossi, <i>University of Rome</i> ; Marco Balucani, <i>University of Rome</i>	
Flexible, Transparent Electronics for Biomedical Applications	494
Michael Klopfer, <i>University of California, Irvine</i> ; Chris Cordonier, <i>Kanto Gakuin University</i> ; Koutoku Inoue, <i>Kanto Gakuin University</i> ; G.-P. Li, <i>University of California, Irvine</i> ; Hideo Honma, <i>Kanto Gakuin University</i> ; Mark Bachman, <i>University of California, Irvine</i>	
Epidermal Electronics for Seamless Monitoring of Biopotential Signals	500
Mitul Dalal, <i>mc10, Inc.</i> ; Conor Rafferty, <i>mc10, Inc.</i> ; Yung-Yu Hsu, <i>mc10, Inc.</i> ; Henry Wei, <i>mc10, Inc.</i> ; Kevin Dowling, <i>mc10, Inc.</i> ; Briana Morey, <i>mc10, Inc.</i> ; Greg Levesque, <i>mc10, Inc.</i> ; Gil Huppert, <i>mc10, Inc.</i> ; Brian Elolampi, <i>mc10, Inc.</i> ; Dan Davis, <i>mc10, Inc.</i>	
Sensor Integrated Microfluidics for Compact Micro-Reactors	504
Erik Jung, <i>Fraunhofer IZM</i> ; Martin Blechert, <i>Fraunhofer IZM</i> ; Victoria Schuldt, <i>Fraunhofer IZM</i> ; Moritz Hubl, <i>Fraunhofer IZM</i> ; Leopold Georg, <i>Technical University Berlin</i> ; Klaus-Dieter Lang, <i>Technical University Berlin</i>	
3-Axis MEMS Accelerometer-Based Implantable Heart Monitoring System with Novel Fixation Method	510
Fjodors Tjulkins, <i>Vestfold University College</i> ; Anh Tuan Thai Nguyen, <i>Vestfold University College</i> ; Nils Hoivik, <i>Vestfold University College</i> ; Knut E. Aasmundtveit, <i>Vestfold University College</i> ; Erik Andreassen, <i>Vestfold University College</i> ; Lars Hoff, <i>Vestfold University College</i> ; Kristin Imenes, <i>Vestfold University College</i>	
3D IPAC - A New Passives and Actives Concept for Ultra-Miniaturized Electronic and Bioelectronic Functional Modules	517
P. Markondeya Raj, <i>Georgia Institute of Technology</i> ; Uei-Ming Jow, <i>Georgia Institute of Technology</i> ; Jinxiang Dai, <i>Inframat Corporation</i> ; K.P. Murali, <i>Georgia Institute of Technology</i> ; Himani Sharma, <i>Georgia Institute of Technology</i> ; Dibyajat Mishra, <i>Georgia Institute of Technology</i> ; T. Danny Xiao, <i>Inframat Corporation</i> ; Saumya Gandhi, <i>Georgia Institute of Technology</i> ; Maysam Ghovanloo, <i>Georgia Institute of Technology</i> ; Rao Tummala, <i>Georgia Institute of Technology</i>	
Anti-Counterfeit, Miniaturized, and Advanced Electronic Substrates for Medical Device Applications	523
Rabindra N. Das, <i>Endicott Interconnect Technologies, Inc.</i> ; Frank D. Egitto, <i>Endicott Interconnect Technologies, Inc.</i> ; How Lin, <i>Endicott Interconnect Technologies, Inc.</i>	
12: High Brightness LEDs and Materials	
Chairs:	Henning Schroeder, <i>Fraunhofer IZM</i> Stefan Weiss, <i>Oclaro Switzerland GmbH</i>
Very High Power Density LED Modules on Aluminum Substrates with Embedded Water Cooling	529
Marc Schneider, <i>Karlsruhe Institute of Technology</i> ; Benjamin Leyrer, <i>Karlsruhe Institute of Technology</i> ; Christian Herbold, <i>Karlsruhe Institute of Technology</i> ; Stefan Maikowske, <i>Karlsruhe Institute of Technology</i>	

LED Matrix Light Source for Adaptive Driving Beam Applications	535
Gordon Elger, <i>Philips Technology GmbH</i> ; Benno Spinger, <i>Philips Technology GmbH</i> ; Nico Bienen, <i>Philips Technology GmbH</i> ; Nils Benter, <i>Philips Technology GmbH</i>	
Substrate Reflectivity Study for High Brightness LED Package	541
Chieh-Lung Lai, <i>Siliconware Precision Industries Co., Ltd.</i> ; Song-Chun Wu, <i>Siliconware Precision Industries Co., Ltd.</i> ; Jui-Feng Lai, <i>Siliconware Precision Industries Co., Ltd.</i> ; Hsien-Wen Chen, <i>Siliconware Precision Industries Co., Ltd.</i>	
Evaluation of Directed Self-Assembly Process for LED Assembly on Flexible Substrates	546
Anton Tkachenko, <i>Rensselaer Polytechnic Institute</i> ; Robert F. Karlicek, Jr., <i>Rensselaer Polytechnic Institute</i> ; James J.-Q. Lu, <i>Rensselaer Polytechnic Institute</i>	
High Refractive Index and Transparency Nanocomposites as Encapsulant for High Brightness LED Packaging	553
Yan Liu, <i>Georgia Institute of Technology</i> ; Ziyin Lin, <i>Georgia Institute of Technology</i> ; Xueying Zhao, <i>Georgia Institute of Technology</i> ; Kyoung-Sik Moon, <i>Georgia Institute of Technology</i> ; Sehoon Yoo, <i>Korea Institute of Industrial Technology</i> ; J. Choi, <i>EI Lighting Co. Ltd.</i> ; C.P. Wong, <i>Georgia Institute of Technology, Chinese University of Hong Kong</i>	
Realization of High-Quality Light Output Based on a Novel LED Packaging	557
Shuiming Li, <i>Huazhong University of Science & Technology</i> ; Kai Wang, <i>Guangdong Real Faith Opto-Electronic Co., Ltd.</i> ; Fei Chen, <i>Huazhong University of Science & Technology</i> ; Yi Sun, <i>Huazhong University of Science & Technology</i> ; Bin Cao, <i>Huazhong University of Science & Technology</i> ; Sheng Liu, <i>Huazhong University of Science & Technology</i>	
Quasi-Conformal Phosphor Dispensing on LED for White Light Illumination	563
S.W. Ricky Lee, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Xungao Guo, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Daoyuan Niu, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Jeffery C.C. Lo, <i>Hong Kong University of Science & Technology (HKUST)</i>	
13: 3D Processing and Technology	
Chairs: Christopher Bower, <i>Semprius, Inc.</i>	
Erik Jung, <i>Fraunhofer IZM</i>	
TSV Last for Hybrid Pixel Detectors: Application to Particle Physics and Imaging Experiments	568
D. Henry, <i>CEA-LETI</i> ; J. Alozy, <i>CERN</i> ; A. Berthelot, <i>CEA-LETI</i> ; R. Cuchet, <i>CEA-LETI</i> ; C. Chantre, <i>CEA-LETI</i> ; M. Campbell, <i>CERN</i>	
Dielectric Stack Engineering for Via-Reveal Passivation	576
Kath Crook, <i>SPTS Technologies</i> ; Mark Carruthers, <i>SPTS Technologies</i> ; Daniel Archard, <i>SPTS Technologies</i> ; Steve Burgess, <i>SPTS Technologies</i> ; Keith Buchanan, <i>SPTS Technologies</i>	
Low-Cost Micrometer-Scale Silicon Vias (SVs) Fabrication by Metal-Assisted Chemical Etching (MaCE) and Carbon Nanotubes (CNTs) Filling	581
Liyi Li, <i>Georgia Institute of Technology</i> ; Yagang Yao, <i>Georgia Institute of Technology</i> ; Ziyin Lin, <i>Georgia Institute of Technology</i> ; Yan Liu, <i>Georgia Institute of Technology</i> ; C.P. Wong, <i>Georgia Institute of Technology, Chinese University of Hong Kong</i>	
Impact of Post-Plating Anneal and Through-Silicon Via Dimensions on Cu Pumping	586
Joke De Messemaeker, <i>IMEC</i> ; Olalla Varela Pedreira, <i>IMEC</i> ; Bart Vandeveld, <i>IMEC</i> ; Harold Philipsen, <i>IMEC</i> ; Ingrid De Wolf, <i>IMEC</i> ; Eric Beyne, <i>IMEC</i> ; Kristof Croes, <i>IMEC</i>	
A Quick-Turn 3D Structured ASIC Platform for Cost-Sensitive Applications	592
John Teifel, <i>Sandia National Laboratories</i> ; Richard S. Flores, <i>Sandia National Laboratories</i> ; Robert Jarecki, <i>Sandia National Laboratories</i> ; Todd Bauer, <i>Sandia National Laboratories</i> ; Subhash L. Shinde, <i>Sandia National Laboratories</i>	

TSV-Based Quartz Crystal Resonator Using 3D Integration and Si Packaging Technologies	599
Jian-Yu Shih, <i>National Chiao Tung University</i> ; Yen-Chi Chen, <i>TXC Corporation</i> ; Cheng-Hao Chiang, <i>National Chiao Tung University</i> ; Chih-Hung Chiu, <i>TXC Corporation</i> ; Yu-Chen Hu, <i>National Chiao Tung University</i> ; Chung-Lun Lo, <i>TXC Corporation</i> ; Chi-Chung Chang, <i>TXC Corporation</i> ; Kuan-Neng Chen, <i>National Chiao Tung University</i>	
Total Cost Effective Scallop Free Si Etching for 2.5D & 3D TSV Fabrication Technologies in 300mm Wafer	605
Yasuhiro Morikawa, <i>ULVAC, Inc.</i> ; Takahide Murayama, <i>ULVAC, Inc.</i> ; Yuu Nakamuta, <i>ULVAC, Inc.</i> ; Toshiyuki Sakuishi, <i>ULVAC, Inc.</i> ; Akiyoshi Suzuki, <i>ULVAC, Inc.</i> ; Koukou Suu, <i>ULVAC, Inc.</i>	
14: 3D TSV Interconnects Reliability	
Chairs:	Akitsu Shigetou, <i>National Institute for Materials Science</i> Scott Savage, <i>Medtronic Microelectronics Center</i>
Model for Prediction of Package-on-Package Warpage and the Effect of Process and Material Parameters	608
Pradeep Lall, <i>Auburn University</i> ; Kewal Patel, <i>Auburn University</i> ; Vikalp Narayan, <i>Auburn University</i>	
Design for Reliability of Multi-Layer Thin Film Stretchable Interconnects	623
Yung-Yu Hsu, <i>mc10, Inc.</i> ; Kylie Lucas, <i>mc10, Inc.</i> ; Dan Davis, <i>mc10, Inc.</i> ; Rooz Ghaffari, <i>mc10, Inc.</i> ; Brian Elolampi, <i>mc10, Inc.</i> ; Mitul Dalal, <i>mc10, Inc.</i> ; John Work, <i>mc10, Inc.</i> ; Stephen Lee, <i>mc10, Inc.</i> ; Conor Rafferty, <i>mc10, Inc.</i> ; Kevin Dowling, <i>mc10, Inc.</i>	
A More Practical Method of Predicting Flip Chip Solder Bump Electromigration Reliability	629
Shiguo (Richard) Rao, <i>Vitesse Semiconductor Corporation</i>	
Improvement of the Reliability of TSV Interconnections by Controlling the Crystallinity of Electroplated Copper Thin Films	635
Ryosuke Furuya, <i>Tohoku University</i> ; Chuanhong Fan, <i>Tohoku University</i> ; Osamu Asai, <i>Tohoku University</i> ; Ken Suzuki, <i>Tohoku University</i> ; Hideo Miura, <i>Tohoku University</i>	
Characterization of Plasticity and Stresses in TSV Structures in Stacked Dies Using Synchrotron X-Ray Microdiffraction	641
Tengfei Jiang, <i>University of Texas, Austin</i> ; Chenglin Wu, <i>University of Texas, Austin</i> ; Peng Su, <i>Cisco Systems, Inc.</i> ; Xi Liu, <i>Cisco Systems, Inc.</i> ; Pierre Chia, <i>Cisco Systems, Inc.</i> ; Li Li, <i>Cisco Systems, Inc.</i> ; Ho-Young Son, <i>SK Hynix Inc.</i> ; Jae-Sung Oh, <i>SK Hynix Inc.</i> ; Kwang-Yoo Byun, <i>SK Hynix Inc.</i> ; Nam-Seog Kim, <i>SK Hynix Inc.</i> ; Jay Im, <i>University of Texas, Austin</i> ; Rui Huang, <i>University of Texas, Austin</i> ; Paul S. Ho, <i>University of Texas, Austin</i>	
X-Ray Micro-Beam Diffraction Determination of Full-Stress Tensors in Cu TSVs	648
Chukwudi Okoro, <i>NIST</i> ; Lyle E. Levine, <i>NIST</i> ; Ruqing Xu, <i>Argonne National Laboratory</i> ; Jonathan Z. Tischler, <i>Argonne National Laboratory</i> ; Wenjun Liu, <i>Argonne National Laboratory</i> ; Oleg Kirillov, <i>NIST</i> ; Klaus Hummler, <i>SEMATECH</i> ; Yaw S. Obeng, <i>NIST</i>	
Effect of Metal Finishing Fabricated by Electro and Electro-less Plating Process on Reliability Performance of 30µm-Pitch Solder Micro Bump Interconnection	653
Jing-Ye Juang, <i>Industrial Technology Research Institute (ITRI)</i> ; Shin-Yi Huang, <i>Industrial Technology Research Institute (ITRI)</i> ; Chau-Jie Zhan, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Min Lin, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Wei Huang, <i>Industrial Technology Research Institute (ITRI)</i> ; Chia-Wen Fan, <i>Industrial Technology Research Institute (ITRI)</i> ; Su-Ching Chung, <i>Industrial Technology Research Institute (ITRI)</i> ; Su-Mei Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Jon-Shiou Peng, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Lan Lu, <i>Industrial Technology Research Institute (ITRI)</i> ; Pai-Cheng Chang, <i>Industrial Technology Research Institute (ITRI)</i> ; Mei-Lun Wu, <i>Industrial Technology Research Institute (ITRI)</i> ; John H. Lau, <i>Industrial Technology Research Institute (ITRI)</i>	

15: Enabling Technologies for Flip Chip Assembly

Chairs: Valerie Oberson, *IBM Canada*
Tom Poulin, *Aerie Engineering*

Low-k ILD Reliability through Chip-Package Assembly: Engineering Appropriate Stress Tests and Process Certification Criteria	660
Sudarshan Rangaraj, <i>Intel Corporation</i> ; Jeffrey Hicks, <i>Intel Corporation</i> ; Michael O'Day, <i>Intel Corporation</i> ; Ankur Aggarwal, <i>Intel Corporation</i> ; Terri Wilson, <i>Intel Corporation</i> ; Ramanarayanan Panchapakesan, <i>Intel Corporation</i> ; Rohit Grover, <i>Intel Corporation</i> ; Guotao Wang, <i>Intel Corporation</i>	
Flip Chip Assembly Method Employing Differential Heating/Cooling for Large Dies with Coreless Substrates	667
Katsuyuki Sakuma, <i>IBM Microelectronics Division</i> ; Edmund Blackshear, <i>IBM Microelectronics Division</i> ; Krishna Tunga, <i>IBM Microelectronics Division</i> ; Chenzhou Lian, <i>IBM Microelectronics Division</i> ; Shidong Li, <i>IBM Microelectronics Division</i> ; Marcus Interrante, <i>IBM Microelectronics Division</i> ; Oswald Mantilla, <i>IBM Microelectronics Division</i> ; Jae-Woong Nah, <i>IBM T.J. Watson Research Center</i>	
3D Integration of CMOS Image Sensor with Coprocessor Using TSV Last and Micro-Bumps Technologies	674
P. Coudrain, <i>STMicroelectronics</i> ; D. Henry, <i>CEA-LETI</i> ; A. Berthelot, <i>CEA-LETI</i> ; J. Charbonnier, <i>CEA-LETI</i> ; S. Verrun, <i>CEA-LETI</i> ; R. Franiatte, <i>CEA-LETI</i> ; N. Bouzaida, <i>CEA-LETI</i> ; G. Cibrario, <i>CEA-LETI</i> ; F. Calmon, <i>Institut des Nanotechnologies de Lyon, INSA</i> ; I. O'Connor, <i>Institut des Nanotechnologies de Lyon, INSA</i> ; T. Lacrevez, <i>Université de Savoie</i> ; L. Fourneaud, <i>Université de Savoie</i> ; B. Flechet, <i>Université de Savoie</i> ; N. Chevrier, <i>STMicroelectronics</i> ; A. Farcy, <i>STMicroelectronics</i> ; O. Le-Briz, <i>STMicroelectronics</i>	
Methodology to Evaluate Pre-Applied Underfill Materials with Concurrent Flux Capability for Ultra-Fine Pitch Solder-Based Interconnects	683
Sunoo Kim, <i>SEMATECH</i> ; Seth Kruger, <i>SEMATECH</i> ; Brian Sapp, <i>SEMATECH</i> ; Ho Hyung Lee, <i>State University of New York, Binghamton</i> ; Seungbae Park, <i>State University of New York, Binghamton</i> ; Sitaram Arkalgud, <i>SEMATECH</i>	
No Clean Flux Technology for Large Die Flip Chip Packages	688
Akihiro Horibe, <i>IBM Research – Tokyo</i> ; Kang-Wook Lee, <i>IBM Research – Watson</i> ; Keishi Okamoto, <i>IBM Research – Tokyo</i> ; Hiroyuki Mori, <i>IBM Research – Tokyo</i> ; Yasumitsu Orii, <i>IBM Research – Tokyo</i> ; Yuki Nishizako, <i>NAMICS Corporation</i> ; Osamu Suzuki, <i>NAMICS Corporation</i> ; Yukio Shirai, <i>NAMICS Corp.</i>	
Ultra Large System-in-Package (SiP) Module and Novel Packaging Solution for Networking Applications	694
Mudasir Ahmad, <i>Cisco Systems, Inc.</i> ; Mohan Nagar, <i>Cisco Systems, Inc.</i> ; Weidong Xie, <i>Cisco Systems, Inc.</i> ; Miguel Jimarez, <i>Amkor Technology, Inc.</i> ; ChangGyun Ryu, <i>Amkor Technology, Inc.</i>	
Low-Cost E-Band Flip-Chip Assembly and Materials	702
Katarina Boustedt, <i>Ericsson AB</i> ; Per Ligander, <i>Ericsson AB</i>	
16: Interconnect Reliability	
Chairs: Vikas Gupta, <i>Texas Instruments</i> TzCheng Chiu, <i>National Cheng Kung University</i>	
Electromigration of Solder Balls for Wafer-Level Packaging with Different Under Bump Metallurgy and Redistribution Layer Thickness	707
Christine Hau-Riege, <i>Qualcomm, Inc.</i> ; Beth Keser, <i>Qualcomm, Inc.</i> ; You-Wen Yau, <i>Qualcomm, Inc.</i> ; Steve Bezuk, <i>Qualcomm, Inc.</i>	
Electromigration Reliability and Current Carrying Capacity of Various WLCSP Interconnect Structures	714
Ahmer Syed, <i>Amkor Technology, Inc.</i> ; Karthikeyan Dhandapani, <i>Amkor Technology, Inc.</i> ; Christopher Berry, <i>Amkor Technology, Inc.</i> ; Robert Moody, <i>Amkor Technology, Inc.</i> ; Riki Whiting, <i>Amkor Technology, Inc.</i>	

Reliability Modeling and Testing of Advanced QFN Packages	725
Li Li, <i>Cisco Systems, Inc.</i>	
An Improved Model for Predicting Fatigue-Crack Propagation Behaviors in Multiple Solder Bumps on a BGA Package	731
Takeshi Terasaki, <i>Hitachi, Ltd.</i> ; Hisashi Tanie, <i>Hitachi, Ltd.</i> ; Tetsuya Nakatsuka, <i>Hitachi, Ltd.</i> ; Satoshi Kurauchi, <i>Hitachi Storage Manufacturing, Ltd.</i> ; Tadayuki Yamashita, <i>Hitachi Storage Mfg, Ltd.</i> ; Yuichi Furusawa, <i>Hitachi Storage Manufacturing, Ltd.</i> ; Hironori Imai, <i>SCSK Corporation</i>	
Grain Structure Evolution and its Impact on the Fatigue Reliability of Lead-Free Solder Joints in BGA Packaging Assembly	740
Huili Xu, <i>University of Texas, Arlington</i> ; Tae-Kyu Lee, <i>Cisco Systems, Inc.</i> ; Choong-Un Kim, <i>University of Texas, Arlington</i>	
Failure Analysis of Thermally and Mechanically Stressed Plastic Core Solder Balls	748
M.M.V. Taklo, <i>SINTEF</i> ; J. Seland Graff, <i>SINTEF</i> ; D. Nilsen Wright, <i>SINTEF</i> ; H. Kristiansen, <i>Conpart AS</i> ; L. Hoff, <i>Vestfold University College</i> ; K. Waaler, <i>WesternGeco AS</i>	
An Eco-Friendly Cu-Zn Wetting Layer for Highly Reliable Solder Joints	755
Young Min Kim, <i>Hanyang University</i> ; Sun-Chul Kim, <i>Hanyang University</i> ; Young-Ho Kim, <i>Hanyang University</i>	
17: Adhesives and Underfill Materials	
Chairs:	Stephanie Potisek, <i>Dow Chemical</i> Dwayne Shirley, <i>Texas Instruments Inc.</i>
Innovative Wafer-Level Encapsulation & Underfill Material for Silicon Interposer Application	761
C. Ferrandon, <i>CEA-LETI</i> ; A. Jouve, <i>CEA-LETI</i> ; S. Joblot, <i>STMicroelectronics</i> ; Y. Lamy, <i>CEA-LETI</i> ; A. Schreiner, <i>CEA-LETI</i> ; P. Montmeat, <i>CEA-LETI</i> ; M. Pellat, <i>CEA-LETI</i> ; M. Argoud, <i>CEA-LETI</i> ; F. Fournel, <i>CEA-LETI</i> ; G. Simon, <i>CEA-LETI</i> ; S. Cheramy, <i>CEA-LETI</i>	
Wafer Level Underfill Entrapment in Solder Joint During Thermocompression: Simulation and Experimental Validation	768
A. Taluy, <i>STMicroelectronics, University of Grenoble</i> ; A. Jouve, <i>CEA-LETI</i> ; S. Joblot, <i>STMicroelectronics</i> ; R. Franiatte, <i>CEA-LETI</i> ; J. Bertheau, <i>STMicroelectronics</i> ; A. Farcy, <i>STMicroelectronics</i> ; S. Chéramy, <i>CEA-LETI</i> ; N. Sillon, <i>CEA-LETI</i> ; P. Ancy, <i>STMicroelectronics</i> ; A. Sylvestre, <i>University of Grenoble</i>	
Novel Surface Modification of Nanosilica for Low Stress Underfill	773
Ziyin Lin, <i>Georgia Institute of Technology</i> ; Yan Liu, <i>Georgia Institute of Technology</i> ; Kyoung-Sik Moon, <i>Georgia Institute of Technology</i> ; C.P. Wong, <i>Georgia Institute of Technology, Chinese University of Hong Kong</i>	
The Optimization of the Composition of Non-Conductive Film and the Lamination to Wafer	778
Satomi Kawamoto, <i>NAMICS Corporation</i> ; Atsushi Saito, <i>NAMICS Corporation</i> ; Yoshihide Fukuhara, <i>NAMICS Corporation</i> ; Hiromi Sone, <i>NAMICS Corporation</i> ; Masaaki Hoshiyama, <i>NAMICS Corporation</i>	
Development of Highly Reliable Flip-Chip Bonding Technology Using Non-Conductive Adhesives (NCAs) for 20 μm Pitch Application	785
Sun-Chul Kim, <i>Hanyang University</i> ; Myung-Hwan Hong, <i>Hanyang University</i> ; Ji-Hyun Lee, <i>Hanyang University</i> ; Young-Ho Kim, <i>Hanyang University</i>	
High Thermal Conductive Adhesive Film for Cu and Al Plate Adhesion in Power Electronics Package	790
Toshihisa Nonaka, <i>Toray Industries, Inc.</i> ; Akira Shimada, <i>Toray Industries, Inc.</i> ; Koichi Aoki, <i>Toray Industries, Inc.</i> ; Noburo Asahi, <i>Toray Industries, Inc.</i>	

The Effect of Coating Thickness on the Electrical Performance of Novel Isotropic Conductive Adhesives Prepared Using Metallised Polymer Micro-Spheres	796
S. Jain, <i>Loughborough University</i> ; D.C. Whalley, <i>Loughborough University</i> ; M. Cottrill, <i>Loughborough University</i> ; T. Helland, <i>MosaicSolutions AS</i> ; H. Kristiansen, <i>Conpart AS</i> ; K. Redford, <i>Conpart AS</i> ; C. Liu, <i>Loughborough University</i>	
18: Thermal and Mechanical Modeling and Simulation	
Chairs: Erdogan Madenci, <i>University of Arizona</i> Xuejun Fan, <i>Lamar University</i>	
Modeling and Experimental Study of Thin Bond Line Thermal Interface Material Failure	803
Shidong Li, <i>IBM Corporation</i> ; Tuhin Sinha, <i>IBM Corporation</i> ; Taryn J. Davis, <i>IBM Corporation</i> ; Kamal Sikka, <i>IBM Corporation</i> ; Paul Bodenweber, <i>IBM Corporation</i>	
3D vs 2D Modeling of the Effect of Die Size on Delamination in Encapsulated IC Packages	807
Siow Ling Ho, <i>Institute of Microelectronics, A*STAR</i> ; Andrew A.O. Tay, <i>National University of Singapore</i>	
Effective Package-On-Package Warpage DOE Design with Analytical Method	813
Shengmin Wen, <i>Amkor Technology, Inc.</i> ; Wei Lin, <i>Amkor Technology, Inc.</i>	
Damage Pre-Cursor Based Assessment of Impact of High Temperature Storage on Reliability of Leadfree Electronics	817
Pradeep Lall, <i>Auburn University</i> ; Kazi Mirza, <i>Auburn University</i> ; Mahendra Harsha, <i>Auburn University</i> ; Jeff Suhling, <i>Auburn University</i> ; Kai Goebel, <i>NASA Ames Research Center</i>	
A Preliminary Solder Joint Life Prediction Model by Experiment and Simulation for Translation of Use Condition to Temperature Cycling Test Condition	827
Ru Han, <i>Intel Corporation</i> ; Min Pei, <i>Intel Corporation</i> ; Alan Lucero, <i>Intel Corporation</i> ; Daeil Kwon, <i>Intel Corporation</i> ; Yun Ge, <i>Intel Corporation</i> ; Richard Harries, <i>Intel Corporation</i> ; Pardeep Bhatti, <i>Intel Corporation</i> ; Tieyu Zheng, <i>Intel Corporation</i>	
Use of Compliant Interconnects for Drop Impact Isolation	835
Wei Chen, <i>Georgia Institute of Technology</i> ; Anirudh Bhat, <i>Georgia Institute of Technology</i> ; Suresh K. Sitaraman, <i>Georgia Institute of Technology</i>	
Prediction of Board-Level Performance of WLCSP	840
Yumin Liu, <i>Fairchild Semiconductor Corporation</i> ; Yong Liu, <i>Fairchild Semiconductor Corporation</i>	
19: Interposer Characterization	
Chairs: Matthew Yao, <i>Rockwell Collins</i> Katsuyuki Sakuma, <i>IBM Corporation</i>	
High Speed Signaling Performance of Multilevel Wiring on Glass Substrates for 2.5-D Integrated Circuit and Optoelectronic Integration	846
Xiaoxiong Gu, <i>IBM T.J. Watson Research Center</i> ; Renato Rimolo-Donadio, <i>IBM T.J. Watson Research Center</i> ; Russell Budd, <i>IBM T.J. Watson Research Center</i> ; Christian W. Baks, <i>IBM T.J. Watson Research Center</i> ; Lavanya Turlapati, <i>IBM T.J. Watson Research Center</i> ; Christopher Jahnes, <i>IBM T.J. Watson Research Center</i> ; Daniel M. Kuchta, <i>IBM T.J. Watson Research Center</i> ; Clint L. Schow, <i>IBM T.J. Watson Research Center</i> ; Frank Libsch, <i>IBM T.J. Watson Research Center</i>	
Unified Methodology for Heterogeneous Integration with CoWoS Technology	852
Yi-Lin Chuang, <i>Taiwan Semiconductor Manufacturing Company</i> ; Chung-Sheng Yuan, <i>Taiwan Semiconductor Manufacturing Company</i> ; Ji-Jan Chen, <i>Taiwan Semiconductor Manufacturing Company</i> ; Ching-Fang Chen, <i>Taiwan Semiconductor Manufacturing Company</i> ; Ching-Shun Yang, <i>Taiwan Semiconductor Manufacturing Company</i> ; Wei-Pin Changchien, <i>Taiwan Semiconductor Manufacturing Company</i> ; Charles C.C. Liu, <i>Taiwan Semiconductor Manufacturing Company</i> ; Frank Lee, <i>Taiwan Semiconductor Manufacturing Company</i>	

Power Comparison of 2D, 3D, and 2.5D Interconnect Solutions and Power Optimization of Interposer Interconnects	860
M. Ataul Karim, <i>North Carolina State University</i> ; Paul D. Franzon, <i>North Carolina State University</i> ; Anil Kumar, <i>SEMATECH, Inc.</i>	
Large Silicon, Glass and Low CTE Organic Interposers to Printed Wiring Board SMT Interconnections Using Copper Microwire Arrays	867
Xian Qin, <i>Georgia Institute of Technology</i> ; Sebastian Gottschall, <i>Georgia Institute of Technology</i> ; Nitesh Kumbhat, <i>Georgia Institute of Technology</i> ; P. Markondeya Raj, <i>Georgia Institute of Technology</i> ; Sungjin Kim, <i>Georgia Institute of Technology</i> ; Venky Sundaram, <i>Georgia Institute of Technology</i> ; Rao Tummala, <i>Georgia Institute of Technology</i>	
Towards Alternative Technologies for Fine Pitch Interconnects	872
J.P. Colonna, <i>CEA-LETI</i> ; R. Segaud, <i>CEA-LETI</i> ; F. Marion, <i>CEA-LETI</i> ; M. Volpert, <i>CEA-LETI</i> ; A. Garnier, <i>CEA-LETI</i> ; L. Di Cioccio, <i>CEA-LETI</i> ; Y. Beillard, <i>CEA-LETI, STMicroelectronics</i> ; S. Mermoz, <i>CEA-LETI,</i> <i>STMicroelectronics</i> ; F. De Crécy, <i>CEA-LETI</i> ; C. Laviron, <i>CEA-LETI</i> ; S. Chéramy, <i>CEA-LETI</i>	
Warpage Control of Silicon Interposer for 2.5D Package Application	879
Kei Murayama, <i>Shinko Electric Industries Co., Ltd.</i> ; Mitsuhiro Aizawa, <i>Shinko Electric Industries Co., Ltd.</i> ; Koji Hara, <i>Shinko Electric Industries Co., Ltd.</i> ; Masahiro Sunohara, <i>Shinko Electric Industries Co., Ltd.</i> ; Ken Miyairi, <i>Shinko Electric Industries Co., Ltd.</i> ; Kenichi Mori, <i>Shinko Electric Industries Co., Ltd.</i> ; Jean Charbonnier, <i>CEA-LETI</i> ; Myriam Assous, <i>CEA-LETI</i> ; Jean-Philippe Bally, <i>CEA-LETI</i> ; Gilles Simon, <i>CEA-LETI</i> ; Mitsutoshi Higashi, <i>Shinko Electric Industries Co., Ltd.</i>	
Development and Characterization of a Through-Multilayer TSV Integrated SRAM Module	885
Yunhui Zhu, <i>Peking University</i> ; Shenglin Ma, <i>Xiamen University, Peking University</i> ; Xin Sun, <i>Peking</i> <i>University</i> ; Runiu Fang, <i>Peking University</i> ; Xiao Zhong, <i>Peking University</i> ; Yuan Bian, <i>Peking University</i> ; Meng Chen, <i>Peking University</i> ; Jing Chen, <i>Peking University</i> ; Min Miao, <i>Peking University, Beijing Information</i> <i>Science and Technology University</i> ; Wengao Lu, <i>Peking University</i> ; Yufeng Jin, <i>Peking University</i>	
20: Challenges in 3D Integration	
Chairs: Andy Tseng, <i>Advanced Semiconductor Engineering, Inc.</i> Wei Koh, <i>Pacrim Technology</i>	
Flux-Assisted Self-Assembly with Microbump Bonding for 3D Heterogeneous Integration	891
Yuka Ito, <i>Tohoku University, Sumitomo Bakelite Co., Ltd.</i> ; Takafumi Fukushima, <i>Tohoku University</i> ; Kang-Wook Lee, <i>Tohoku University</i> ; Koji Choki, <i>Sumitomo Bakelite Co., Ltd.</i> ; Tetsu Tanaka, <i>Tohoku</i> <i>University</i> ; Mitsumasa Koyanagi, <i>Tohoku University</i>	
Micro-Bump Bondability Design Guidelines for High Throughput 2.5D/3D IC Assemblies	897
Chang-Lin Yeh, <i>Advanced Semiconductor Engineering, Inc.</i> ; Yung-Yi Yeh, <i>Advanced Semiconductor</i> <i>Engineering, Inc.</i> ; Jen-Chieh Kao, <i>Advanced Semiconductor Engineering, Inc.</i> ; Tong Hong Wang, <i>Advanced Semiconductor Engineering, Inc.</i> ; Chang-Chi Lee, <i>Advanced Semiconductor Engineering, Inc.</i> ; Ho-Ming Tong, <i>Advanced Semiconductor Engineering, Inc.</i>	
Assembly Process Qualification and Reliability Evaluations for Heterogeneous 2.5D FPGA with HiCTE Ceramic	904
Ganesh Hariharan, <i>Xilinx, Inc.</i> ; Raghunandan Chaware, <i>Xilinx, Inc.</i> ; Laurene Yip, <i>Xilinx, Inc.</i> ; Inderjit Singh, <i>Xilinx, Inc.</i> ; Kenny Ng, <i>Xilinx, Inc.</i> ; S.Y. Pai, <i>Xilinx, Inc.</i> ; Myongseob Kim, <i>Xilinx, Inc.</i> ; Henley Liu, <i>Xilinx, Inc.</i> ; Suresh Ramalingam, <i>Xilinx, Inc.</i>	
Thermally Enhanced Pre-Applied Underfills for 3D Integration	909
Akihiro Horibe, <i>IBM Research – Tokyo</i> ; Keishi Okamoto, <i>IBM Research – Tokyo</i> ; Hiroyuki Mori, <i>IBM</i> <i>Research – Tokyo</i> ; Yasumitsu Orii, <i>IBM Research – Tokyo</i> ; Kohichiro Kawate, <i>Sumitomo 3M, Ltd.</i> ; Yorinobu Takamatsu, <i>Sumitomo 3M, Ltd.</i> ; Hiroko Akiyama, <i>Sumitomo 3M, Ltd.</i>	

Integration Challenges of TSV Backside Via Reveal Process	915
Bo Kai Huang, <i>Siliconware Precision Industries Co., Ltd.</i> ; Chien Ming Lin, <i>Siliconware Precision Industries Co., Ltd.</i> ; Shin Jiang Huang, <i>Siliconware Precision Industries Co., Ltd.</i> ; Ching Wen Chiang, <i>Siliconware Precision Industries Co., Ltd.</i> ; Pin Cheng Huang, <i>Siliconware Precision Industries Co., Ltd.</i> ; Guang Xin Chen, <i>Siliconware Precision Industries Co., Ltd.</i> ; Chun Chieh Chao, <i>Siliconware Precision Industries Co., Ltd.</i> ; Chun Hung Lu, <i>Siliconware Precision Industries Co., Ltd.</i>	
Yield and Reliability in 3D Interconnect and WLP - Ultra Thin Chip Stacking	918
H. Luesebrink, <i>PVA Tepla AG</i> ; G. Parès, <i>CEA-LETI</i> ; A. Attard, <i>Besi Austria GmbH</i> ; F. Schnegg, <i>Besi Austria GmbH</i> ; G. Klug, <i>Disco Hi-Tech Europe GmbH</i>	
Package-on-Package with Very Fine Pitch Interconnects for High Bandwidth	922
Ilyas Mohammed, <i>Invensas Corporation</i> ; Reynaldo Co, <i>Invensas Corporation</i> ; Rajesh Katkar, <i>Invensas Corporation</i>	
21: Advanced Substrate and Flip Chip Packaging	
Chairs: YoungGon Kim, <i>IDT</i>	
Raj N. Master, <i>Microsoft Corporation</i>	
Nano-Silica Composite Laminate	929
Katsura Hayashi, <i>Kyocera Corporation</i> ; Tadashi Nagasawa, <i>Kyocera Corporation</i> ; Keisaku Matsumoto, <i>Kyocera Corporation</i> ; Shinya Kawai, <i>Kyocera Corporation</i>	
Copper-Filled Anodic Aluminum Oxide: A Potential Substrate Material for a High-Density Interconnection	937
Michio Horiuchi, <i>Shinko Electric Industries Co., Ltd.</i> ; Yuuichi Matsuda, <i>Shinko Electric Industries Co., Ltd.</i> ; Yasue Tokutake, <i>Shinko Electric Industries Co., Ltd.</i> ; Ryo Fukasawa, <i>Shinko Electric Industries Co., Ltd.</i> ; Tsuyoshi Kobayashi, <i>Shinko Electric Industries Co., Ltd.</i>	
Development of a Low CTE Chip Scale Package	944
Tomoyuki Yamada, <i>Kyocera SLC Technologies Corporation</i> ; Masahiro Fukui, <i>Kyocera SLC Technologies Corporation</i> ; Kenji Terada, <i>Kyocera SLC Technologies Corporation</i> ; Masaaki Harazono, <i>Kyocera SLC Technologies Corporation</i> ; Charles Reynolds, <i>IBM Corporation</i> ; Jean Audet, <i>IBM Corporation</i> ; Sushumna Iruvanti, <i>IBM Corporation</i> ; Hsichang Liu, <i>IBM Corporation</i> ; Scott Moore, <i>IBM Corporation</i> ; Yi Pan, <i>IBM Corporation</i> ; Hongqing Zhang, <i>IBM Corporation</i>	
Thermally Enhanced and Thin Profile Flip Chip Packages for Tablet Processor Applications	949
Hamid Eslampour, <i>STATS ChipPAC, Ltd.</i> ; Mukul Joshi, <i>STATS ChipPAC, Ltd.</i> ; KyungOe Kim, <i>STATS ChipPAC, Ltd.</i> ; Sun Wei, <i>STATS ChipPAC, Ltd.</i> ; JaeHan Chung, <i>STATS ChipPAC, Ltd.</i> ; TaeWoo Lee, <i>STATS ChipPAC, Ltd.</i> ; HangChul Choi, <i>STATS ChipPAC, Ltd.</i> ; Roger Emigh, <i>STATS ChipPAC, Ltd.</i>	
Development of Chip-on-Chip with Face to Face Technology as a Low Cost Alternative for 3D Packaging	955
J. Sutanto, <i>Amkor Technology, Inc.</i> ; D.H. Kang, <i>Amkor Technology Korea</i> ; S.Y. Ma, <i>Amkor Technology Korea</i> ; J.H. Yoon, <i>Amkor Technology Korea</i> ; K.S. Oh, <i>Amkor Technology Korea</i> ; M. Oh, <i>Amkor Technology Korea</i> ; K.R. Park, <i>Amkor Technology, Inc.</i> ; R. Lanzone, <i>Amkor Technology, Inc.</i> ; R. Huemoeller, <i>Amkor Technology, Inc.</i>	
Mechanical and Board Level Reliability Considerations of Lidless Flip Chip BGA Packaging	966
Shin Low, <i>Xilinx, Inc.</i> ; Inderjit Singh, <i>Xilinx, Inc.</i> ; Ganesh Hariharan, <i>Xilinx, Inc.</i> ; Laurene Yip, <i>Xilinx, Inc.</i> ; Nael Zohni, <i>Xilinx, Inc.</i> ; Mulugeta Abteu, <i>Sanmina-SCI Corp.</i> ; Gowri Shankar Solaiappan, <i>Sanmina-SCI Corp.</i> ; Vineeth Vair, <i>Sanmina-SCI Corp.</i> ; Shane Lewis, <i>Sanmina-SCI Corp.</i>	
Mechanical Properties of Sn-Bi Bumps on Flexible Substrate	971
Min-Su Kim, <i>University of Science & Technology, Korea Institute of Industrial Technology (KITECH)</i> ; Yong-Ho Ko, <i>Korea Institute of Industrial Technology (KITECH), KAIST</i> ; Sehoon Yoo, <i>Korea Institute of Industrial Technology (KITECH)</i> ; Chang-Woo Lee, <i>Korea Institute of Industrial Technology (KITECH)</i>	

22: Solder and Material Characterization

Chairs: Dongming He, *Qualcomm, Inc.*
Donna M. Noctor, *Siemens Industry, Inc.*

- Reliability and Failure Mechanism of Solder Joints in Thermal Cycling Tests** 976
Babak Arfaei, *Universal Instruments Corporation, State University of New York, Binghamton*;
Sam Mahin-Shirazi, *State University of New York, Binghamton*; Shantanu Joshi, *State University of New York, Binghamton*; Martin Anselm, *Universal Instruments Corporation*; Peter Borgesen, *State University of New York, Binghamton*; Eric Cotts, *State University of New York, Binghamton*;
James Wilcox, *IBM Corporation*; Richard Coyle, *Alcatel-Lucent*
- Correlation of Reliability Models Including Aging Effects with Thermal Cycling Reliability Data** 986
Mohammad Motalab, *Auburn University*; Muhannad Mustafa, *Auburn University*; Jeffrey C. Suhling, *Auburn University*; Jiawei Zhang, *Auburn University*; John Evans, *Auburn University*; Michael J. Bozack, *Auburn University*; Pradeep Lall, *Auburn University*
- Comparison of IMC Growth in Flip-Chip Assemblies with 100- and 200- μ m-Pitch SAC305 Solder Joints** 1005
Ye Tian, *Huazhong University of Science and Technology, Georgia Institute of Technology*; Xi Liu, *Georgia Institute of Technology*; Justin Chow, *Georgia Institute of Technology*; Yi Ping Wu, *Huazhong University of Science and Technology*; Suresh K. Sitaraman, *Georgia Institute of Technology*
- Reliability and Shear Strength of 42Sn-57Bi-1Ag (Wt.%) Lead-Free Solder Joints after Thermal Aging and Salt Spray Testing** 1010
M. Mostofizadeh, *Tampere University of Technology*; J. Pippola, *Tampere University of Technology*;
L. Frisk, *Tampere University of Technology*
- Plastic Deformation Effect on Sn Whisker Growth in Electroplated Sn and Sn-Ag Solders** 1018
Sung K. Kang, *IBM T.J. Watson Research Center*; Jaewon Chang, *KAIST*; Jae-Ho Lee, *Hongik University*; Keun-Soo Kim, *Hoseo University*; Hyuck Mo Lee, *KAIST*
- Effect of NCFs with Zn-Nanoparticles on the Interfacial Reactions of 40 μ m Pitch Cu Pillar/Sn-Ag Bump for TSV Interconnection** 1024
Ji-Won Shin, *KAIST*; Yong-Won Choi, *KAIST*; Young Soon Kim, *KAIST*; Un Byung Kang, *Samsung Electronics Company, Ltd.*; Young Kun Jee, *Samsung Electronics Company, Ltd.*;
Kyung-Wook Paik, *KAIST*
- Advanced In Situ Characterization of TIM1 Reliability** 1031
Peng Li, *Intel Corporation*; Yongmei Liu, *Intel Corporation*; Alfred La Mar, *Intel Corporation*;
Deepak Goyal, *Intel Corporation*
- ## 23: Novel Technologies
- Chairs:** Yoichi Taira, *IBM Japan*
Choong Kooi Chee, *Intel Corporation*
- Reduced Graphene Oxide Based Schottky Diode on Flex Substrate for Microwave Circuit Applications** 1037
Amanpreet Kaur, *Michigan State University*; Xianbo Yang, *Michigan State University*;
Kyoung Youl Park, *Michigan State University*; Premjeet Chahal, *Michigan State University*
- Ultra-Thin, Self-Healing Decoupling Capacitors on Thin Glass Interposers Using High Surface Area Electrodes** 1043
Parthasarathi Chakraborti, *Georgia Institute of Technology*; Himani Sharma, *Georgia Institute of Technology*;
P. Markondeya Raj, *Georgia Institute of Technology*; Rao Tummala, *Georgia Institute of Technology*
- Electrochemical Assembly of SAM on Copper for Epoxy/Copper Adhesion Improvement** 1048
Stephen C.T. Kwok, *Hong Kong University of Science & Technology (HKUST)*; Matthew M.F. Yuen, *Hong Kong University of Science & Technology (HKUST)*

Chip-Side-Healing as a Basis for Robust Bare-Chip Assemblies	1054
Matthias Steiert, <i>University of Freiburg</i> ; Jürgen Wilde, <i>University of Freiburg</i>	
Development of Biocompatible Coatings on Flexible Electronics	1060
Rabindra N. Das, <i>Endicott Interconnect Technologies, Inc.</i> ; Frank D. Egitto, <i>Endicott Interconnect Technologies, Inc.</i> ; Mark Poliks, <i>Endicott Interconnect Technologies, Inc.</i>	
Development of Low Temperature Sintered Nano Silver Pastes Using MO Technology and Resin Reinforcing Technology	1066
Koji Sasaki, <i>NAMICS Corporation</i> ; Noritsuka Mizumura, <i>NAMICS Corporation</i>	
Facile Synthesis of BaTiO₃ Nanorods and Their Shape Effects on the Dielectric Constants of Polymer Composites	1071
Pengli Zhu, <i>Chinese Academy of Sciences</i> ; Rong Sun, <i>Chinese Academy of Sciences</i> ; Ching-ping Wong, <i>Chinese University of Hong Kong</i>	
24: Power and Signal Integrity	
Chairs: Kemal Aygun, <i>Intel Corporation</i> Daniel de Araujo, <i>Nimbic, Inc.</i>	
Simultaneous Switching Noise Model by Distributed Power Port and Ground Current Capture	1076
Seunghyun Hwang, <i>NVIDIA Corporation</i> ; Daehyun Chung, <i>NVIDIA Corporation</i> ; Venkat Satagopan, <i>NVIDIA Corporation</i> ; Sunil Sudhakaran, <i>NVIDIA Corporation</i> ; Daniel Lin, <i>NVIDIA Corporation</i> ; Fathi Moghadam, <i>NVIDIA Corporation</i>	
System Level Signal and Power Integrity Analysis for 3200Mbps DDR4 Interface	1081
June Feng, <i>Altera Corporation</i> ; Bipin Dhavale, <i>Altera Corporation</i> ; Janani Chandrasekhar, <i>Altera Corporation</i> ; Yuri Tretiakov, <i>Altera Corporation</i> ; Dan Oh, <i>Altera Corporation</i>	
Analysis of Power Integrity and its Jitter Impact in a 4.3Gbps Low-Power Memory Interface	1087
Hai Lan, <i>Rambus, Inc.</i> ; Xinhai Jiang, <i>Rambus, Inc.</i> ; Jihong Ren, <i>Rambus, Inc.</i>	
Unconditionally Stable Explicit Method for the Fast 3-D Simulation of On-Chip Power Distribution Network	1094
Tadatoshi Sekine, <i>Shizuoka University</i> ; Hideki Asai, <i>Shizuoka University</i>	
Power Delivery Network Analysis of 3D Double-Side Glass Interposers for High Bandwidth Applications	1100
Gokul Kumar, <i>Georgia Institute of Technology</i> ; Srikrishna Sitaraman, <i>Georgia Institute of Technology</i> ; Jonghyun Cho, <i>KAIST</i> ; Sung Jin Kim, <i>Georgia Institute of Technology</i> ; Venky Sundaram, <i>Georgia Institute of Technology</i> ; Joungho Kim, <i>KAIST</i> ; Rao Tummala, <i>Georgia Institute of Technology</i>	
Fast Voltage Drop Modeling of Power Grid with Application to Silicon Interposer Analysis	1109
En-Xiao Liu, <i>Institute of High Performance Computing, A*STAR</i> ; Er-Ping Li, <i>Institute of High Performance Computing, A*STAR</i>	
Power Delivery Modeling for 3D Systems with Non-Uniform TSV Distribution	1115
Huanyu He, <i>Rensselaer Polytechnic Institute</i> ; Zheng Xu, <i>IBM Microelectronics Division</i> ; Xiaoxiong Gu, <i>IBM T.J. Watson Research Center</i> ; Jian-Qiang Lu, <i>Rensselaer Polytechnic Institute</i>	
25: 3D Microbump Structures and Silicon to Silicon Bonding	
Chairs: Tom Gregorich, <i>Broadcom Corporation</i> Li Li, <i>Cisco Systems, Inc.</i>	
Key Elements for Sub-50μm Pitch Micro Bump Processes	1122
J. De Vos, <i>IMEC</i> ; L. Bogaerts, <i>IMEC</i> ; T. Buisson, <i>IMEC</i> ; C. Gerets, <i>IMEC</i> ; G. Jamieson, <i>IMEC</i> ; K. Vandersmissen, <i>IMEC</i> ; A. La Manna, <i>IMEC</i> ; E. Beyne, <i>IMEC</i>	

Microstructural and Morphological Characterization of SnAgCu Micro-Bumps for Integration in 3D Interconnects	1127
J. Bertheau, <i>STMicroelectronics</i> ; P. Bleuët, <i>CEA-LETI</i> ; Roland Pantel, <i>STMicroelectronics</i> ; J. Charbonnier, <i>CEA-LETI</i> ; F. Hodaj, <i>SIMaP-UMR</i> ; P. Coudrain, <i>STMicroelectronics</i> ; N. Hotellier, <i>STMicroelectronics</i>	
Mechanism of Low-Temperature Copper-to-Copper Direct Bonding for 3D TSV Package Interconnection	1133
J. Cho, <i>State University of New York, Binghamton</i> ; S. Yu, <i>State University of New York, Binghamton</i> ; M.P.C. Roma, <i>State University of New York, Binghamton</i> ; S. Maganty, <i>State University of New York, Binghamton</i> ; S. Park, <i>State University of New York, Binghamton</i> ; E. Bersch, <i>SEMATECH</i> ; C. Kim, <i>SEMATECH</i> ; B. Sapp, <i>SEMATECH</i>	
Room-Temperature High-Density Interconnection Using Ultrasonic Bonding of Cone Bump for Heterogeneous Integration	1141
Takanori Shuto, <i>Kyushu University</i> ; Keiichiro Iwanabe, <i>Kyushu University</i> ; Li Jing Qiu, <i>Kyushu University</i> ; Tanemasa Asano, <i>Kyushu University</i>	
Low Temperature (<180°C) Wafer-Level and Chip-Level In-to-Cu and Cu-to-Cu Bonding for 3D Integration	1146
Yu-Sasn Chien, <i>National Chiao Tung University</i> ; Yan-Pin Huang, <i>National Chiao Tung University</i> ; Ruoh-Ning Tzeng, <i>National Chiao Tung University</i> ; Ming-Shaw Shy, <i>Advanced Semiconductor Engineering, Inc.</i> ; Teu-Hua Lin, <i>Advanced Semiconductor Engineering, Inc.</i> ; Kou-Hua Chen, <i>Advanced Semiconductor Engineering, Inc.</i> ; Ching-Te Chuang, <i>National Chiao Tung University</i> ; Wei Hwang, <i>National Chiao Tung University</i> ; Jin-Chern Chiou, <i>National Chiao Tung University</i> ; Chi-Tsung Chiu, <i>Advanced Semiconductor Engineering, Inc.</i> ; Ho-Ming Tong, <i>Advanced Semiconductor Engineering, Inc.</i> ; Kuan-Neng Chen, <i>National Chiao Tung University</i>	
Hybrid Au-Au Bonding Technology Using Planar Adhesive Structure for 3D Integration	1153
Masatsugu Nimura, <i>Waseda University</i> ; Jun Mizuno, <i>Waseda University</i> ; Akitsu Shigetou, <i>National Institute for Materials Science (NIMS)</i> ; Katsuyuki Sakuma, <i>IBM Corporation</i> ; Hiroshi Ogino, <i>Nissan Chemical Industries</i> ; Tomoyuki Enomoto, <i>Nissan Chemical Industries</i> ; Shuichi Shoji, <i>Waseda University</i>	
High Throughput Cu-Cu Bonding by Non-Thermo-Compression Method	1158
Chuan Seng Tan, <i>Nanyang Technological University</i> ; Gang Yih Chong, <i>Nanyang Technological University</i>	
26: High Speed Interconnects and Power Distribution in 3D Integration	
Chairs:	Rockwell Hsu, <i>Tiva Systems Inc. at Cisco Systems, Inc.</i> Amit P. Agrawal, <i>Cisco Systems, Inc.</i>
A DC-Blocking Dielectric Waveguide Via Design for High Speed Signaling at Millimeter Wave Frequencies	1165
Jose A. Hejase, <i>IBM Corporation</i> ; Nanju Na, <i>IBM Corporation</i> ; Nam Pham, <i>IBM Corporation</i> ; Lloyd Walls, <i>IBM Corporation</i>	
Characterization of Power Delivery Network by Using Optimized Power/Ground Port Termination Impedance	1171
Seungyong (Brian) Baek, <i>Cisco Systems, Inc.</i> ; Jiali Lai, <i>University of California, Davis</i> ; Amit Agrawal, <i>Cisco Systems, Inc.</i>	
An Air-Dielectric Via Structure for 20Gbps+ Board Connectors	1175
Xin Wu, <i>Molex, Inc.</i> ; David Dunham, <i>Molex, Inc.</i> ; Nanju Na, <i>IBM Corporation</i> ; Jose A. Hejase, <i>IBM Corporation</i>	

Multi-Layer Adaptive Power Management Architecture for TSV 3DIC Applications	1179
Ming-Hung Chang, <i>National Chiao Tung University, Advanced Semiconductor Engineering (ASE) Group</i> ; Wei-Chih Hsieh, <i>National Chiao Tung University</i> ; Pei-Chen Wu, <i>National Chiao Tung University</i> ; Ching-Te Chuang, <i>National Chiao Tung University</i> ; Kuan-Neng Chen, <i>National Chiao Tung University</i> ; Chen-Chao Wang, <i>Advanced Semiconductor Engineering (ASE) Group</i> ; Chun-Yen Ting, <i>Advanced Semiconductor Engineering (ASE) Group</i> ; Kua-Hua Chen, <i>Advanced Semiconductor Engineering (ASE) Group</i> ; Chi-Tsung Chiu, <i>Advanced Semiconductor Engineering (ASE) Group</i> ; Ho-Ming Tong, <i>Advanced Semiconductor Engineering (ASE) Group</i> ; Wei Hwang, <i>National Chiao Tung University, Advanced Semiconductor Engineering (ASE) Group</i>	
Wideband and Scalable Equivalent-Circuit Model for Differential Through Silicon Vias with Measurement Verification	1186
Kuan-Chung Lu, <i>National Sun Yat-Sen University</i> ; Tzyy-Sheng Horng, <i>National Sun Yat-Sen University</i>	
Wideband Ultralow Power Distribution Network Impedance Evaluation of Decoupling Capacitor Embedded Interposers for 3-D Integrated LSI System	1190
Katsuya Kikuchi, <i>National Institute of Advanced Industrial Science and Technology (AIST)</i> ; Toshio Gomyo, <i>Association of Super-Advanced Electronic Technologies (ASET)</i> ; Toshikazu Ookubo, <i>Association of Super-Advanced Electronic Technologies (ASET)</i> ; Masahiro Aoyagi, <i>National Institute of Advanced Industrial Science and Technology (AIST)</i> ; Toshio Sudo, <i>Shibaura Institute of Technology</i> ; Kanji Otsuka, <i>Meisei University</i>	
A New Approach to Power Integrity with Thinfilm Capacitors in 3D IPAC Functional Module	1197
Saumya Gandhi, <i>Georgia Institute of Technology</i> ; P. Markondeya Raj, <i>Georgia Institute of Technology</i> ; Venky Sundaram, <i>Georgia Institute of Technology</i> ; Himani Sharma, <i>Georgia Institute of Technology</i> ; Madhavan Swaminathan, <i>Georgia Institute of Technology</i> ; Rao Tummala, <i>Georgia Institute of Technology</i>	
27: Wafer Level and Embedded Packaging	
Chairs: Luu T. Nguyen, <i>Texas Instruments</i> Altaf Hasan, <i>Intel Corporation</i>	
A Study of Wafer Level Package Board Level Reliability	1204
Steven Xu, <i>Qualcomm Technologies, Inc.</i> ; Beth Keser, <i>Qualcomm Technologies, Inc.</i> ; Christine Hau-Riege, <i>Qualcomm Technologies, Inc.</i> ; Steve Bezuk, <i>Qualcomm Technologies, Inc.</i> ; You-Wen Yau, <i>Qualcomm Technologies, Inc.</i>	
Optimization of Solder Height and Shape to Improve the Thermo-Mechanical Reliability of Wafer-Level Chip Scale Packages	1210
Su-Chun Yang, <i>Taiwan Semiconductor Manufacturing Company</i> ; Chung-Jung Wu, <i>Taiwan Semiconductor Manufacturing Company</i> ; Da-Yuan Shih, <i>Taiwan Semiconductor Manufacturing Company</i> ; Chih-Hang Tung, <i>Taiwan Semiconductor Manufacturing Company</i> ; Cheng-Chang Wei, <i>Taiwan Semiconductor Manufacturing Company</i> ; Yi-Li Hsiao, <i>Taiwan Semiconductor Manufacturing Company</i> ; Ying-Jui Huang, <i>Taiwan Semiconductor Manufacturing Company</i> ; Douglas Chen-Hua Yu, <i>Taiwan Semiconductor Manufacturing Company</i>	
Wafer Level Packaging for Ultra Thin (6 μm) High Brightness LEDs Using Embedding Technology ...	1219
J. Kleff, <i>Technical University Berlin</i> ; M. Töpper, <i>Fraunhofer IZM</i> ; L. Dietrich, <i>Fraunhofer IZM</i> ; H. Oppermann, <i>Fraunhofer IZM</i> ; S. Herrmann, <i>OSRAM Opto Semiconductors GmbH</i>	
Embedded Capacitors in the Next Generation Processor	1225
Yongki Min, <i>Intel Corporation</i> ; Reynaldo Olmedo, <i>Intel Corporation</i> ; Michael Hill, <i>Intel Corporation</i> ; Kaladhar Radhakrishnan, <i>Intel Corporation</i> ; Kemal Aygun, <i>Intel Corporation</i> ; Mostafa Kabiri-Badr, <i>Intel Corporation</i> ; Rahul Panat, <i>Intel Corporation</i> ; Sriram Dattaguru, <i>Intel Corporation</i> ; Haluk Balkan, <i>Intel Corporation</i>	
3D Power Module with Embedded WLCSP	1230
Shichun Qu, <i>Fairchild Semiconductor</i> ; Jihwan Kim, <i>Fairchild Semiconductor</i> ; Glen Marcus, <i>Fairchild Semiconductor</i> ; Matt Ring, <i>Fairchild Semiconductor</i>	

From Wafer to Panel Level Mold Embedding	1235
T. Braun, <i>Fraunhofer IZM</i> ; K.-F. Becker, <i>Fraunhofer IZM</i> ; S. Voges, <i>Technical University Berlin</i> ; T. Thomas, <i>Technical University Berlin</i> ; R. Kahle, <i>Technical University Berlin</i> ; J. Bauer, <i>Fraunhofer IZM</i> ; R. Aschenbrenner, <i>Fraunhofer IZM</i> ; K.-D. Lang, <i>Technical University Berlin</i>	
Reliability of Embedding Concepts for Discrete Passive Components in Organic Circuit Boards	1243
R. Schwerz, <i>Fraunhofer Institute for Non-Destructive Testing (IZFP-D)</i> ; B. Boehme, <i>Fraunhofer Institute for Non-Destructive Testing (IZFP-D)</i> ; M. Roellig, <i>Fraunhofer Institute for Non-Destructive Testing (IZFP-D)</i> ; K.-J. Wolter, <i>Technical University Dresden</i> ; N. Meyendorf, <i>Fraunhofer Institute for Non-Destructive Testing (IZFP-D)</i>	
28: Drop and Dynamic Mechanical Reliability	
Chairs:	Darvin R. Edwards, <i>Texas Instruments, Inc.</i> Lakshmi N. Ramanathan, <i>Microsoft Corporation</i>
Effect of Strain Rate on Adhesion Strength of Anisotropic Conductive Films (ACF) Joints	1252
J. Meng, <i>University of Maryland</i> ; P. Stark, <i>University of Maryland</i> ; A. Dasgupta, <i>University of Maryland</i> ; M. Sillanpaa, <i>Nokia Corporation</i> ; Esa Hussa, <i>Nokia Corporation</i> ; Jukka P. Seppanen, <i>Nokia Corporation</i> ; Jouni A. Raunio, <i>Nokia Corporation</i> ; Ilkka J. Saarinen, <i>Nokia Corporation</i>	
An Approach to Board-Level Drop Reliability Evaluation with Improved Correlation with Use Conditions	1259
T.T. Mattila, <i>Aalto University</i> ; L. Vajavaara, <i>Aalto University</i> ; J. Hokka, <i>Aalto University</i> ; E. Hussa, <i>Nokia Corporation</i> ; M. Mäkelä, <i>Nokia Corporation</i> ; V. Halkola, <i>Nokia Corporation</i>	
A New and Effective Drop Test Evolution to Next-Gen Handheld Applications	1269
Dongji Xie, <i>Nvidia Corporation</i> ; Ife Hsu, <i>Intel Corporation</i> ; Yingliang Zhou, <i>Huawei Technologies</i> ; Andy Zhang, <i>Texas Instruments, Inc.</i> ; Min Woo, <i>Nvidia Corporation</i> ; Ramgopal Uppalapati, <i>Intel Corporation</i> ; Zhongming Wu, <i>Nvidia Corporation</i> ; Tom McMullen, <i>Nvidia Corporation</i>	
Effect of Aging on High Strain Rate Mechanical Properties of SAC105 and SAC305 Leadfree Alloys ...	1277
Pradeep Lall, <i>Auburn University</i> ; Sandeep Shantaram, <i>Auburn University</i> ; Jeff Suhling, <i>Auburn University</i> ; Dave Locker, <i>US AMRDEC</i>	
Brittle Fracture of Intermetallic Compounds in SAC Solder Joints under High Speed Ball Pull/Pin Pull and Charpy Impact Tests	1294
Chaoran Yang, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Guangsui Xu, <i>Hong Kong University of Science & Technology (HKUST)</i> , <i>South China University of Technology</i> ; S.W. Ricky Lee, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Xinping Zhang, <i>South China University of Technology</i>	
Combined Vibration and Thermal Cycling Fatigue Analysis for SAC305 Lead Free Solder Assemblies	1300
J.H.L. Pang, <i>Nanyang Technological University</i> ; F.L. Wong, <i>Nanyang Technological University</i> ; K.T. Heng, <i>DSO National Laboratories</i> ; Y.S. Chua, <i>DSO National Laboratories</i> ; C.E. Long, <i>DSO National Laboratories</i>	
Effects of Varying Amplitudes on the Fatigue Life of Lead Free Solder Joints	1308
M. Obaidat, <i>State University of New York, Binghamton</i> ; S. Hamasha, <i>State University of New York, Binghamton</i> ; Y. Jaradat, <i>State University of New York, Binghamton</i> ; A. Qasaimeh, <i>State University of New York, Binghamton</i> ; B. Arfaei, <i>Universal Instruments Corporation</i> ; M. Anselm, <i>Universal Instruments Corporation</i> ; P. Borgesen, <i>State University of New York, Binghamton</i>	

29: Substrates

Chairs: Lejun Wang, *Qualcomm*
Daniel D. Lu, *Henkel Corporation*

Site-Selective Fabrication of Patterned Transparent Copper Mesh on Flexible Substrates at Mild Temperature for Green, Low Cost Electronics 1315
Yunxia Jin, *Fudan University*; Dunying Deng, *Fudan University*; Fei Xiao, *Fudan University*

The New Primer with Copper Foil Corresponding to Semi-Additive Process for Package Substrates ... 1320
Hitoshi Onozeki, *Hitachi Chemical Co., Ltd.*; Tsubasa Inoue, *Hitachi Chemical Co., Ltd.*;
Katsuji Yamagishi, *Hitachi Chemical Co., Ltd.*; Takahiro Tanabe, *Hitachi Chemical Co., Ltd.*;
Takayuki Suzuki, *Hitachi Chemical Co., Ltd.*; Kenichi Ikeda, *Hitachi Chemical Co., Ltd.*;
Nobuyuki Ogawa, *Hitachi Chemical Co., Ltd.*

Dielectric Composite Material with Good Performance and Process Ability for Embedding of Active and Passive Components into PCBs 1325
Ryan Park, *Atotech Germany GmbH*; Seunghyun Cho, *Dongyang Mirae University*;
Jürgen Kress, *Atotech Germany GmbH*; Norbert Galster, *Atotech Germany GmbH*

An Innovative Embedded Interposer Carrier for High Density Interconnection 1332
Dyi-Chung Hu, *Unimicron Technology Corporation*; Tzyy-Jang Tseng, *Unimicron Technology Corporation*;
Yu-Hua Chen, *Unimicron Technology Corporation*; Wei-Chung Lo, *Industrial Technology Research Institute (ITRI)*

A Lead-Frame Pre-Mold Coreless Substrate Development 1336
Chang-Yi (Albert) Lan, *Siliconware Precision Industries Co., Ltd.*; C.S. Hsiao, *Siliconware Precision Industries Co., Ltd.*;
Jensen Tsai, *Siliconware Precision Industries Co., Ltd.*; Eason Chen, *Siliconware Precision Industries Co., Ltd.*;
Otis Hung, *Siliconware Precision Industries Co., Ltd.*

DBC Substrate for Si- and SiC-Based Power Electronics Modules: Design, Fabrication and Failure Analysis 1341
Ling Xu, *Huazhong University of Science & Technology*; Yang Zhou, *Huazhong University of Science & Technology*;
Sheng Liu, *Huazhong University of Science & Technology*

A Monolithic Aluminum Circuit Board Structure 1346
Shou-Jen Hsu, *University of California, Irvine*; Chin C. Lee, *University of California, Irvine*

30: Electrical Modeling and Measurements

Chairs: Wendem Beyene, *Rambus Inc.*
Zhaoqing Chen, *IBM Corporation*

System-Level Clock Jitter Modeling for DDR Systems 1350
Yujeong Shim, *Altera Corporation*; Dan Oh, *Altera Corporation*; Chuan Thim Khor, *Altera Corporation*;
Bipin Dhavale, *Altera Corporation*; Sunitha Chandra, *Altera Corporation*; Daniel Chow, *Altera Corporation*;
Weichi Ding, *Altera Corporation*; Kundan Chand, *Altera Corporation*; Aman Aflaki, *Altera Corporation*;
Mayra Sarmiento, *Altera Corporation*

Circuit/Channel Co-Design Methodology for Multimode Signaling 1356
Zhuo Yan, *North Carolina State University*; Paul D. Franzon, *North Carolina State University*;
Kemal Aygün, *Intel Corporation*; Henning Braunsch, *Intel Corporation*

Characterization of a Low-Power 6.4 Gbps DDR DIMM Memory Interface System 1362
Ravi Kollipara, *Rambus, Inc.*; Sam Chang, *Rambus, Inc.*; Chris Madden, *Rambus, Inc.*; Hai Lan, *Rambus, Inc.*;
Liji Gopalakrishnan, *Rambus, Inc.*; Scott Best, *Rambus, Inc.*; Yi Lu, *Rambus, Inc.*;
Sanath Bangalore, *Rambus, Inc.*; Ganapathy E. Kumar, *Rambus, Inc.*; Pravin K. Venkatesan, *Rambus, Inc.*;
Kapil Vyas, *Rambus, Inc.*; Kashinath Prabhu, *Rambus, Inc.*; Kambiz Kaviani, *Rambus, Inc.*;
Michael Bucher, *Rambus, Inc.*; Lei Luo, *Rambus, Inc.*

Characterization, Modeling and Optimization of a 3D Embedded Trench Decoupling Capacitors in Si-RF Interposer	1372
H��l��ne Jacquinet, <i>CEA-LETI</i> ; David Denis, <i>IPDIA</i>	
A Novel and Accurate Methodology for Design and Characterization of Wire-Bond Package Performance for 5-10GHz Applications	1379
Souvik Mukherjee, <i>Texas Instruments, Inc.</i> ; Django Trombley, <i>Texas Instruments, Inc.</i>	
High Frequency Characterization and Analytical Modeling of Through Glass Via (TGV) for 3D Thin-Film Interposer and MEMS Packaging	1385
Cheolbok Kim, <i>University of Florida</i> ; Yong-Kyu Yoon, <i>University of Florida</i>	
PCB Pin-Field Considerations for 40 Gb/s SerDes Channels	1392
Michael J. Degerstrom, <i>Mayo Clinic</i> ; Devon J. Post, <i>Mayo Clinic</i> ; Barry K. Gilbert, <i>Mayo Clinic</i> ; Erik S. Daniel, <i>Mayo Clinic</i>	
31: TSV Innovation and Implementation	
Chairs: Gilles Poupon, <i>CEALETI</i> WeiChung Lo, <i>ITRI</i>	
Through Si Vias Using Liquid Metal Conductors for Re-workable 3D Electronics	1401
George A. Hernandez, <i>Auburn University</i> ; Daniel Martinez, <i>Auburn University</i> ; Charles Ellis, <i>Auburn University</i> ; Michael Palmer, <i>Auburn University</i> ; Michael C. Hamilton, <i>Auburn University</i>	
Backside TSV Protrusions Induced by Thermal Shock and Thermal Cycling	1407
Dingyou Zhang, <i>Rensselaer Polytechnic Institute</i> ; Klaus Hummler, <i>SEMATECH</i> ; Larry Smith, <i>SEMATECH</i> ; James Jian-Qiang Lu, <i>Rensselaer Polytechnic Institute</i>	
Microstructure Investigation of TSV Copper Film	1414
W.N. Putra, <i>Institute of Microelectronics, A*STAR, Nanyang Technological University</i> ; H.Y. Li, <i>Institute of Microelectronics, A*STAR</i> ; A.D. Trigg, <i>Institute of Microelectronics, A*STAR</i> ; C.L. Gan, <i>Nanyang Technological University</i>	
Via-Middle Through-Silicon Via with Integrated Airgap to Zero TSV-Induced Stress Impact on Device Performance	1420
Yann Cival��, <i>IMEC</i> ; Stefaan Van Huylenbroeck, <i>IMEC</i> ; Augusto Redolfi, <i>IMEC</i> ; Wei Guo, <i>IMEC</i> ; Khashayar Babaei Gavan, <i>IMEC</i> ; Patrick Jaenen, <i>IMEC</i> ; Antonio La Manna, <i>IMEC</i> ; Gerald Beyer, <i>IMEC</i> ; Bart Swinnen, <i>IMEC</i> ; Eric Beyne, <i>IMEC</i>	
Design and Fabrication of Ultra Low-Loss, High-Performance 3D Chip-Chip Air-Clad Interconnect Pathway	1425
Erdal Uzunlar, <i>Georgia Institute of Technology</i> ; Rohit Sharma, <i>Indian Institute of Technology Ropar</i> ; Rajarshi Saha, <i>Georgia Institute of Technology</i> ; Vachan Kumar, <i>Georgia Institute of Technology</i> ; Rizwan Bashirullah, <i>University of Florida</i> ; Azad Naeemi, <i>Georgia Institute of Technology</i> ; Paul A. Kohl, <i>Georgia Institute of Technology</i>	
Development of Ultra-Low Capacitance Through-Silicon-Vias (TSVs) with Air-Gap Liner	1433
Qianwen Chen, <i>Tsinghua University</i> ; Cui Huang, <i>Tsinghua University</i> ; Zheyao Wang, <i>Tsinghua University</i>	
TSV Development, Characterization and Modeling for 2.5-D Interposer Applications	1439
J.-R. Tenailleau, <i>IPDIA</i> ; A. Brunet, <i>CEA-LETI</i> ; S. Borel, <i>CEA-LETI</i> ; F. Voiron, <i>IPDIA</i> ; C. Bunel, <i>IPDIA</i>	

32: Thermal and Mechanical Modeling: LED and 3D Structures

Chairs: Suresh K. Sitaraman, *Georgia Institute of Technology*
Sandeep Sane, *Intel Corporation*

- Drop Impact Simulation and Experimental Validation on High Power Light Emitting Diodes Modules** ... 1446
Cao Li, *Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics*;
Tao Peng, *Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics*;
Xuefang Wang, *Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics*;
Mingxiang Chen, *Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics*;
Sheng Liu, *Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics*
- L70 Life Prediction for Solid State Lighting Using Kalman Filter and Extended Kalman Filter Based Models** 1452
Pradeep Lall, *Auburn University*; Junchao Wei, *Auburn University*; Lynn Davis, *RTI International*
- Effect of Temperature Gradient on Moisture Diffusion in High Power Devices and the Applications in LED Packages** 1466
Xuejun Fan, *Lamar University, State Key Lab of Solid-State Lighting*; Cadmus Yuan, *State Key Lab of Solid-State Lighting, Chinese Academy of Sciences*
- Thermal and Mechanical Design and Analysis of 3D IC Interposer with Double-Side Active Chips** 1471
Sheng-Tsai Wu, *Industrial Technology Research Institute (ITRI)*; Heng-Chieh Chien, *Industrial Technology Research Institute (ITRI)*; John H. Lau, *Industrial Technology Research Institute (ITRI)*;
Ming Li, *Rambus, Inc.*; Julia Cline, *Rambus, Inc.*; Mandy Ji, *Rambus, Inc.*
- Comparison of Thermal Performance between Glass and Silicon Interposers** 1480
Sangbeom Cho, *Georgia Institute of Technology*; Yogendra Joshi, *Georgia Institute of Technology*;
Venky Sundaram, *Georgia Institute of Technology*; Yoichiro Sato, *Asahi Glass*;
Rao Tummala, *Georgia Institute of Technology*
- Simulation of Electro-migration through Peridynamics** 1488
Selda Oterkus, *University of Arizona*; John Fox, *University of Arizona*;
Erdogan Madenci, *University of Arizona*
- The Effect of Corner Glue on BGA Package Temperature Cycling Performance: A Modeling Study** 1494
Min Pei, *Intel Corporation*; Ru Han, *Intel Corporation*; Yun Ge, *Intel Corporation*; Sanjay Goyal, *Intel Corporation*;
Venmathy Rajarathinam, *Intel Corporation*; Muffadal Mukadam, *Intel Corporation*
- ### 33: MEMS and Sensor Packaging
- Chairs:** S.W. Ricky Lee, *Hong Kong University of Science and Technology*
James Jian Zhang, *Micron Technology, Inc.*
- Hermetic Wafer Level Packaging of MEMS Components Using Through Silicon Via and Wafer to Wafer Bonding Technologies** 1500
K. Zoschke, *Fraunhofer IZM*; C.-A. Manier, *Fraunhofer IZM*; M. Wilke, *Fraunhofer IZM*; N. Jürgensen, *Fraunhofer IZM*;
H. Oppermann, *Fraunhofer IZM*; D. Ruffieux, *CSEM*; J. Dekker, *VTT Technical Research Centre of Finland*;
Hannele Heikkinen, *VTT Technical Research Centre of Finland*; S. Dalla Piazza, *Micro Crystal AG*;
G. Allegato, *STMicroelectronics*; K.-D. Lang, *Technical University Berlin*
- Size-Free MEMS-IC High-Efficient Integration by Using Carrier Wafer with Self-Assembled Monolayer (SAM) Fine Pattern** 1508
Jian Lu, *AIST*; Hideki Takagi, *AIST*; Yuta Nakano, *AIST, Tokyo University of Science*; Ryutaro Maeda, *AIST*
- Outgassing Characterization of MEMS Thin Film Packaging Materials** 1514
B. Savornin, *CEA-LETI*; X. Baillin, *CEA-LETI*; E. Blanquet, *SIMAP*; I. Nuta, *SIMAP*; D. Saint Patrice, *CEA-LETI*;
P. Nicolas, *CEA-LETI*; P.L. Charvet, *CEA-LETI*; J.L. Pomin, *CEA-LETI*

Surface Compliant Bonding Properties of Low-Temperature Wafer Bonding Using Sub-Micron Au Particles	1519
Hiroyuki Ishida, <i>Suss MicroTec KK</i> ; Toshinori Ogashiwa, <i>Tanaka Kikinzoku Kogyo KK</i> ; Yukio Kanehira, <i>Tanaka Kikinzoku Kogyo KK</i> ; Hiroshi Murai, <i>Tanaka Kikinzoku Kogyo KK</i> ; Takuya Yazaki, <i>Suss MicroTec KK</i> ; Shin Ito, <i>Waseda University</i> ; Jun Mizuno, <i>Waseda University</i>	
Hermetic Wafer-Level Glass Sealing Enabling Reliable Low Cost Sensor Packaging	1524
Ulli Hansen, <i>MSG Lithoglas GmbH</i> ; Simon Maus, <i>MSG Lithoglas GmbH</i> ; Michael Töpper, <i>Fraunhofer IZM</i>	
Cu/Sn SLID Wafer-Level Bonding Optimization	1531
Thi-Thuy Luu, <i>Vestfold University College</i> ; Ani Duan, <i>Vestfold University College</i> ; Kaiying Wang, <i>Vestfold University College</i> ; Knut Aasmundtveit, <i>Vestfold University College</i> ; Nils Hoivik, <i>Vestfold University College</i>	
Reliability of Flip-Chip Technologies for SiC-MEMS Operating at 500°C	1538
Roderich Zeiser, <i>University of Freiburg</i> ; Lukas Lehmann, <i>University of Freiburg</i> ; Volker Fiedler, <i>University of Freiburg</i> ; Juergen Wilde, <i>University of Freiburg</i>	
34: New Developments in Wirebond Technology	
Chairs: Jie Xue, <i>Cisco Systems, Inc.</i>	
Prema Palaniappan, <i>Texas Instruments</i>	
Investigation of Charge Induced Bond Pad Corrosion	1545
Pei-Haw Tsao, <i>Taiwan Semiconductor Manufacturing Company, Ltd.</i> ; Hung-Yu Chiu, <i>Taiwan Semiconductor Manufacturing Company, Ltd.</i> ; H.C. Liao, <i>Taiwan Semiconductor Manufacturing Company, Ltd.</i> ; K.C. Chen, <i>Taiwan Semiconductor Manufacturing Company, Ltd.</i> ; M.C. Sung, <i>Taiwan Semiconductor Manufacturing Company, Ltd.</i> ; Worth Chen, <i>Taiwan Semiconductor Manufacturing Company, Ltd.</i> ; Antai Xu, <i>Taiwan Semiconductor Manufacturing Company, Ltd.</i>	
Effects of Bond Pad Probing for Cu Wire Bond Packages	1549
John D. Beleran, <i>United Test and Assembly Center, Ltd. (UTAC)</i> ; Gaurav Mehta, <i>United Test and Assembly Center, Ltd. (UTAC)</i> ; Ninoy Milanés II, <i>United Test and Assembly Center, Ltd. (UTAC)</i> ; Nathapong Suthiwongsunthorn, <i>United Test and Assembly Center, Ltd. (UTAC)</i> ; Eu Jin Lee, <i>Global Foundries Singapore Pte. Ltd.</i>	
A Study of Free Air Ball Formation in Palladium-Coated Copper and Bare Copper Bonding Wire	1556
Noritoshi Araki, <i>Nippon Micrometal Corporation</i> ; Yasutomo Ichiyama, <i>Nippon Steel Technoresearch Corporation</i> ; Ryo Oishi, <i>Nippon Micrometal Corporation</i> ; Takashi Yamada, <i>Nippon Micrometal Corporation</i>	
Single Chip Plated Ni/Pd over ALCAP Bond Pads for Flip Chip Applications and Prototyping	1564
Brian J. Lewis, <i>Engent, Inc.</i> ; Daniel F. Baldwin, <i>Engent, Inc.</i> ; Paul N. Houston, <i>Engent, Inc.</i> ; Fei Xie, <i>Engent, Inc.</i> ; Le Hang La, <i>Engent, Inc.</i>	
Low Cost Silver Alloy Wire Bonding with Excellent Reliability Performance	1569
C.H. Cheng, <i>Elite Semiconductor Memory Technology, Inc.</i> ; H.L. Hsiao, <i>Tunghai University</i> ; S.I. Chu, <i>Elite Semiconductor Memory Technology, Inc.</i> ; Y.Y. Shieh, <i>Elite Semiconductor Memory Technology, Inc.</i> ; C.Y. Sun, <i>Elite Semiconductor Memory Technology, Inc.</i> ; C. Peng, <i>Elite Semiconductor Memory Technology, Inc.</i>	
Corrosion of the Cu/Al Interface in Cu-Wire-Bonded Integrated Circuits	1574
John Osenbach, <i>LSI Corporation</i> ; B.Q. Wang, <i>LSI Corporation</i> ; Sue Emerich, <i>LSI Corporation</i> ; John DeLucca, <i>LSI Corporation</i> ; Dongmei Meng, <i>LSI Corporation</i>	
Molded Reliability Study for Different Cu Wire Bonding Configurations	1587
Ivy Qin, <i>Kulicke and Soffa Industries, Inc.</i> ; Hui Xu, <i>Kulicke and Soffa Industries, Inc.</i> ; Basil Milton, <i>Kulicke and Soffa Industries, Inc.</i> ; Horst Clauberg, <i>Kulicke and Soffa Industries, Inc.</i> ; Bob Chylak, <i>Kulicke and Soffa Industries, Inc.</i> ; Hidenori Abe, <i>Hitachi Chemical Company, Ltd.</i> ; Dongchul Kang, <i>Hitachi Chemical Company, Ltd.</i> ; Yoshinori Endo, <i>Hitachi Chemical Company, Ltd.</i> ; Masahiko Osaka, <i>Hitachi Chemical Company, Ltd.</i> ; Shinya Nakamura, <i>Hitachi Chemical Company, Ltd.</i>	

35: Solder and Bonding

Chairs: Tieyu Zheng, *Microsoft Corporation*
Myung Jin Yim, *Broadcom Corporation*

- NiFe-Based Ball-Limiting-Metallurgy (BLM) for Microbumps at 50um Pitch in 3D Chip Stacks** 1595
Bing Dang, *IBM T.J. Watson Research Center*; Steven Wright, *IBM T.J. Watson Research Center*;
Joana Maria, *IBM T.J. Watson Research Center*; Cornelia Tsang, *IBM T.J. Watson Research Center*;
Paul Andry, *IBM T.J. Watson Research Center*; Lovell Wiggins, *IBM T.J. Watson Research Center*;
John Knickerbocker, *IBM T.J. Watson Research Center*
- The Growth and Segregation of Intermetallic Compounds in the Bulk of Flip Chip Sn2.4Ag Solder Joint under Electrical Current Stressing** 1600
Wei-Chieh Wang, *National Cheng Kung University*; Kwang-Lung Lin, *National Cheng Kung University*;
Ying-Ta Chiu, *Advanced Semiconductor Engineering, Inc.*; Yi-Shao Lai, *Advanced Semiconductor Engineering, Inc.*
- Voiding Mechanism and Control in BGA Joints with Mixed Solder Alloy System** 1606
Yan Liu, *Indium Corporation*; Derrick Herron, *Indium Corporation*; Joanna Keck, *Indium Corporation*;
Ning-Cheng Lee, *Indium Corporation*
- Low Temperature Camera Module Assembly Using Acrylic-Based Solder ACFs with Ultrasonic-Assisted Thermo-Compression Bonding Method** 1613
Yoo-Sun Kim, *KAIST*; Seung-Ho Kim, *KAIST*; Kyung-Wook Paik, *KAIST*
- High Temperature Ag-In Joints between Si Chips and Aluminum** 1617
Yuan-Yun Wu, *University of California, Irvine*; Chin C. Lee, *University of California, Irvine*
- Failure Mechanisms of Sintered Silver Interconnections for Power Electronic Applications** 1621
Thomas Herboth, *Robert Bosch GmbH*; Michael Guenther, *Robert Bosch GmbH*;
Andreas Fix, *Robert Bosch GmbH*; Juergen Wilde, *University of Freiburg*
- Advanced Materials for Drop in Solution to Pb in High Temp Solders: The Next Generation of Zinc Based Solder Alloy** 1628
Jianxing Li, *Honeywell Electronic Materials*; Bih Wen Fon, *On Semiconductor*;
Shutesh Krishnan, *On Semiconductor*; Brian Knight, *Honeywell Electronic Materials*
- 36: System Components for RF and Millimeter Wave**
- Chairs:** LihTyng Hwang, *National Sun YatSen University*
P. Markondeya Raj, *Georgia Institute of Technology*
- Low Cost BT Organic Material for Wireless 60 GHz Application** 1634
Pouya Talebbeydokhti, *Intel Corporation*; Mohamed A. Megahed, *Intel Corporation*
- Novel Enhancement Techniques for Ultra-High-Performance Conformal Wireless Sensors and "Smart Skins" Utilizing Inkjet-Printed Graphene** 1640
Taoran Le, *Georgia Institute of Technology*; Ziyin Lin, *Georgia Institute of Technology*; C.P. Wong, *Georgia Institute of Technology*; M.M. Tentzeris, *Georgia Institute of Technology*
- High Performance Plastic Molded QFN Package with Ribbon Bonding and a Defective PCB Ground** 1644
Yi-Chieh Lin, *National Sun Yat-Sen University*; Wen-Hsian Lee, *National Sun Yat-Sen University*;
Tzzy-Sheng Horng, *National Sun Yat-Sen University*; Lih-Tyng Hwang, *National Sun Yat-Sen University*

Enhanced Multilayer Organic Packages with Embedded Phased-Array Antennas for 60-GHz Wireless Communications	1650
Xiaoxiong Gu, <i>IBM T.J. Watson Research Center</i> ; Dong Gun Kam, <i>IBM T.J. Watson Research Center</i> ; Duixian Liu, <i>IBM T.J. Watson Research Center</i> ; Maxim Piz, <i>IBM T.J. Watson Research Center</i> ; Alberto Valdes-Garcia, <i>IBM T.J. Watson Research Center</i> ; Arun Natarajan, <i>IBM T.J. Watson Research Center, Oregon State University</i> ; Christian Baks, <i>IBM T.J. Watson Research Center</i> ; Bodhisatwa Sadhu, <i>IBM T.J. Watson Research Center</i> ; Scott K. Reynolds, <i>IBM T.J. Watson Research Center</i>	
Ultra-Miniaturized and Surface-Mountable Glass-Based 3D IPAC Packages for RF Modules	1656
Yoichiro Sato, <i>Asahi Glass Company</i> ; Srikrishna Sitaraman, <i>Georgia Institute of Technology</i> ; Vijay Sukumaran, <i>Georgia Institute of Technology</i> ; Bruce Chou, <i>Georgia Institute of Technology</i> ; Junki Min, <i>Georgia Institute of Technology</i> ; Motoshi Ono, <i>Asahi Glass Company</i> ; Choukri Karoui, <i>STMicroelectronics</i> ; Franck Dosseul, <i>STMicroelectronics</i> ; Christian Nopper, <i>STMicroelectronics</i> ; Madhavan Swaminathan, <i>Georgia Institute of Technology</i> ; Venky Sundaram, <i>Georgia Institute of Technology</i> ; Rao Tummala, <i>Georgia Institute of Technology</i>	
Integration of Piezoelectric Energy Harvesting and Antenna Elements on a Common Substrate	1662
Joshua C. Myers, <i>Michigan State University</i> ; B. Scott Strachan, <i>Michigan State University</i> ; Xianbo Yang, <i>Michigan State University</i> ; Premjeet Chahal, <i>Michigan State University</i>	
Second-Harmonic Nonlinearities in RF Silicon Integrated Passive Devices	1667
Robert Frye, <i>RF Design Consulting, LLC</i> ; Kai Liu, <i>STATS ChipPAC, Inc.</i> ; Robert Melville, <i>Emecon, LLC</i>	
37: Interactive Presentations 1	
Chairs:	Mark Poliks, <i>Endicott Interconnect Technologies, Inc.</i> Mark Eblen, <i>Kyocera America, Inc.</i>
Adaptable and Integrated Packaging Platform for MEMS-Based Combo Sensors Utilizing Innovative Wafer-Level Packaging Technologies	1675
Cheng-Hsiang Liu, <i>Siliconware Precision Industries Co., Ltd.</i> ; Hong-Da Chang, <i>Siliconware Precision Industries Co., Ltd.</i> ; Kuo-Hsiang Li, <i>Siliconware Precision Industries Co., Ltd.</i> ; Chen-Han Lin, <i>Siliconware Precision Industries Co., Ltd.</i> ; Chia-Jung Hsu, <i>Siliconware Precision Industries Co., Ltd.</i> ; Tse-Yuan Lin, <i>Siliconware Precision Industries Co., Ltd.</i> ; Hsin-Hung Chou, <i>Siliconware Precision Industries Co., Ltd.</i> ; Hsiao-Chun Huang, <i>Siliconware Precision Industries Co., Ltd.</i> ; Hsin-Yi Liao, <i>Siliconware Precision Industries Co., Ltd.</i>	
Electrochromic Properties of Tungsten Trioxide Nanostructures	1682
Yi-Hsuan Huang, <i>National Chiao Tung University</i> ; Chung-Jung Hung, <i>National Chiao Tung University</i> ; Tseung-Yuen Tseng, <i>National Chiao Tung University</i>	
Wettability of Sn-Bi and Sn-Ag-Cu Lead-Free Solder Pastes on Electroplated Co-P Films	1686
Donghua Yang, <i>Tsinghua University</i> ; Nianduan Lu, <i>Tsinghua University</i> ; Liangliang Li, <i>Tsinghua University</i>	
Enhanced Thermal Transport of Hexagonal Boron Nitride Filled Polymer Composite by Magnetic Field-Assisted Alignment	1692
Ziyin Lin, <i>Georgia Institute of Technology</i> ; Yan Liu, <i>Georgia Institute of Technology</i> ; Kyoung-Sik Moon, <i>Georgia Institute of Technology</i> ; Ching-Ping Wong, <i>Georgia Institute of Technology, Chinese University of Hong Kong</i>	
Small Diameter Via Filling Electrodeposition by Periodical Reverse Current	1697
Taro Hayashi, <i>Osaka Prefecture University</i> ; Kazuo Kondo, <i>Osaka Prefecture University</i> ; Takeyasu Saito, <i>Osaka Prefecture University</i> ; Naoki Okamoto, <i>Osaka Prefecture University</i> ; Masayuki Yokoi, <i>Osaka Prefecture University</i> ; Minoru Takeuchi, <i>Nitto Boseki Co., Ltd.</i> ; Masaru Bunya, <i>Nitto Boseki Co., Ltd.</i> ; Masao Marunaka, <i>ShinMaywa Industries, Ltd.</i> ; Takayuki Tsuchiya, <i>ShinMaywa Industries, Ltd.</i>	
Moisture Induced Swelling in Epoxy Moulding Compounds	1703
H. Walter, <i>Fraunhofer IZM</i> ; O. Hölck, <i>Fraunhofer IZM</i> ; H. Dobrinski, <i>Hella Fahrzeugkomponenten GmbH</i> ; J. Stuermann, <i>Hella Fahrzeugkomponenten GmbH</i> ; T. Braun, <i>Fraunhofer IZM</i> ; J. Bauer, <i>Fraunhofer IZM</i> ; O. Wittler, <i>Fraunhofer IZM</i> ; K.D. Lang, <i>Fraunhofer IZM, Technical University Berlin</i>	

Fine Pitch Flex-on-Flex (FOF) Assembly Using Nanofiber Solder Anisotropic Conductive Films (ACFs) and Ultrasonic Bonding Method	1709
Sang Hoon Lee, <i>KAIST</i> ; Kyung Lim Suk, <i>KAIST</i> ; Kyung-Wook Paik, <i>KAIST</i>	
Flux Function Added Solder Anisotropic Conductive Films (ACFs) for High Power and Fine Pitch Assemblies	1713
Seung-Ho Kim, <i>KAIST</i> ; Yongwon Choi, <i>KAIST</i> ; Yoosun Kim, <i>KAIST</i> ; Kyung-Wook Paik, <i>KAIST</i>	
Microwave Induced Plasma Decapsulation of Stressed and Delaminated High Pin-Count Copper Wire Bonded IC Packages	1717
J. Tang, <i>Delft University of Technology</i> ; C.H. Chen, <i>Advanced Semiconductor Engineering, Inc.</i> ; S.K. Liang, <i>Advanced Semiconductor Engineering, Inc.</i> ; E.G.J. Reinders, <i>MASER Engineering B.V.</i> ; C.Th.A. Revenberg, <i>MASER Engineering B.V.</i> ; J.B.J. Schelen, <i>Delft University of Technology</i> ; C.I.M. Beenakker, <i>Delft University of Technology</i>	
Glass Carrier Wafers for The Silicon Thinning Process for Stack IC Applications	1724
Aric Shorey, <i>Corning, Inc.</i> ; Bor Kai Wang, <i>Corning, Inc.</i> ; Rachel Lu, <i>Corning, Inc.</i>	
Versatile Z-Axis Interconnection-Based Coreless Technology Solutions for Next Generation Packaging	1728
R.N. Das, <i>Endicott Interconnect Technologies, Inc.</i> ; F.D. Egitto, <i>Endicott Interconnect Technologies, Inc.</i> ; J.M. Lauffer, <i>Endicott Interconnect Technologies, Inc.</i> ; Evan Chenelly, <i>Endicott Interconnect Technologies, Inc.</i> ; M.D. Polliks, <i>Endicott Interconnect Technologies, Inc.</i>	
Oxidation Resistance and Joining Properties of Cr-Doped Zn Bonding for SiC Die-Attachment	1734
S.W. Park, <i>Osaka University</i> ; T. Sugahara, <i>Osaka University</i> ; S. Nagao, <i>Osaka University</i> ; K. Sugauma, <i>Osaka University</i>	
Thermomechanical Reliability of Ag Flake Paste for Die-Attached Power Devices in Thermal Cycling	1740
Soichi Sakamoto, <i>Osaka University</i> ; Shijo Nagao, <i>Osaka University</i> ; Katsuaki Sugauma, <i>Osaka University</i>	
A Breakthrough in Power Electronics Reliability – New Die Attach and Wire Bonding Materials	1746
Thomas Krebs, <i>Heraeus Material Technologies GmbH & Co. KG</i> ; Susanne Duch, <i>Heraeus Material Technologies GmbH & Co. KG</i> ; Wolfgang Schmitt, <i>Heraeus Material Technologies GmbH & Co. KG</i> ; Steffen Kötter, <i>Heraeus Material Technologies GmbH & Co. KG</i> ; Peter Prenosil, <i>Heraeus Material Technologies GmbH & Co. KG</i> ; Sven Thomas, <i>Heraeus Material Technologies GmbH & Co. KG</i>	
Bath Chemistry and Copper Overburden as Influencing Factors of the TSV Annealing	1753
P. Saettler, <i>Technical University Dresden</i> ; M. Boettcher, <i>FhG ASSID</i> ; Catharina Rudolph, <i>FhG ASSID</i> ; K.-J. Wolter, <i>Technical University Dresden</i>	
Nonlinear Viscoelastic Constitutive Model for Organic Laminate Substrate	1759
Tz-Cheng Chiu, <i>National Cheng Kung University</i> ; Yao-Yu Chan, <i>National Cheng Kung University</i> ; Yi-Shao Lai, <i>Advanced Semiconductor Engineering, Inc.</i>	
Effect of Processing Factors on Dielectric Properties of BaTiO₃/Hyperbranched Polyester Core-Shell Nanoparticles	1767
Warda Benhadjala, <i>University of Bordeaux</i> ; Isabelle Bord-Majek, <i>University of Bordeaux</i> ; Laurent Béchou, <i>University of Bordeaux</i> ; Ephraim Suhir, <i>University of California, Santa Cruz</i> ; Matthieu Buet, <i>Polyrise SAS</i> ; Fabien Rougé, <i>Polyrise SAS</i> ; Vincent Gaud, <i>Polyrise SAS</i> ; Yves Ousten, <i>University of Bordeaux</i>	
Strength of Solid-State Silver Bonding between Copper	1773
Yi-Ling Chen, <i>University of California, Irvine</i> ; Chin C. Lee, <i>University of California, Irvine</i>	
Effect of Pad Design (SMD/NSMD), Via-in-Pad, and Reflow Profile Parameters on Voiding During the Lead-Free Solder Bumping Process	1777
Ganesh Pandiarajan, <i>State University of New York, Binghamton</i> ; Satyanarayan Iyer, <i>SMART Modular Technologies, Inc.</i> ; Gurudutt Chennagiri, <i>SMART Modular Technologies, Inc.</i> ; Ross Havens, <i>State University of New York, Binghamton</i> ; Krishnaswami Srihari, <i>State University of New York, Binghamton</i>	

Growth and Strength of the Solid Solution Phase (Ag) with Indium	1783
Yuan-Yun Wu, <i>University of California, Irvine</i> ; Chin C. Lee, <i>University of California, Irvine</i>	
Assessment of Solder Pad Cratering Strength Using Cold Pin Pull Test Method with Pre-Fabricated Pin Arrays	1788
Qiming Zhang, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Chaoran Yang, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Mian Tao, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Fubin Song, <i>Celestica</i> ; S.W. Ricky Lee, <i>Hong Kong University of Science & Technology (HKUST)</i>	
Reliability Study of Isotropic Electrically Conductive Adhesives under Thermal Cycling Testing	1794
Laura Frisk, <i>Tampere University of Technology</i> ; Sanna Lahokallio, <i>Tampere University of Technology</i> ; Milad Mostofizadeh, <i>Tampere University of Technology</i> ; Janne Kiilunen, <i>Tampere University of Technology</i> ; Kirsi Saarinen, <i>Tampere University of Technology</i>	
Ethylene-Vinyl Acetate as a Low Cost Encapsulant for Hybrid Electronic and Fluidic Circuits	1800
Sarkis Babikian, <i>University of California, Irvine</i> ; Wesley A. Cox-Muranami, <i>University of California, Irvine</i> ; Edward Nelson, <i>University of California, Irvine</i> ; G.P. Li, <i>University of California, Irvine</i> ; Mark Bachman, <i>University of California, Irvine</i>	
Noise Coupling of Through-Via in Silicon and Glass Interposer	1806
Manho Lee, <i>KAIST</i> ; Jonghyun Cho, <i>KAIST</i> ; Joohee Kim, <i>KAIST</i> ; Joungho Kim, <i>KAIST</i> ; Jiseong Kim, <i>KAIST</i>	
38: Interactive Presentations 2	
Chairs:	Swapan Bhattacharya, <i>Georgia Institute of Technology</i> Nam Pham, <i>IBM Corporation</i>
Fine-Pitch Backside Via-Last TSV Process with Optimization on Temporary Glue and Bonding Conditions	1811
Erh-Hao Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Tzu-Chien Hsu, <i>Industrial Technology Research Institute (ITRI)</i> ; Cha-Hsin Lin, <i>Industrial Technology Research Institute (ITRI)</i> ; Pei-er Tzeng, <i>Industrial Technology Research Institute (ITRI)</i> ; Chung-Chih Wang, <i>Industrial Technology Research Institute (ITRI)</i> ; Shang-Chun Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Jui-Chin Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Chien-Chou Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Chen Hsin, <i>Industrial Technology Research Institute (ITRI)</i> ; Po-Chih Chang, <i>Industrial Technology Research Institute (ITRI)</i> ; Yiu-Hsiang Chang, <i>Industrial Technology Research Institute (ITRI)</i> ; Shin-Chiang Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Ming Lin, <i>Industrial Technology Research Institute (ITRI)</i> ; Sue-Chen Liao, <i>Industrial Technology Research Institute (ITRI)</i> ; Tzu-Kun Ku, <i>Industrial Technology Research Institute (ITRI)</i>	
Investigation of Micromachined LTCC Functional Modules for High-Density 3D SIP Based on LTCC Packaging Platform	1815
Min Miao, <i>Beijing Information Science and Technology University, Peking University</i> ; Yufeng Jin, <i>Peking University</i> ; Runiu Fang, <i>Peking University</i> ; Fangqing Mu, <i>43rd Institute of China Electronics Technology Group Corporation</i> ; Shichao Guo, <i>Peking University</i> ; Xiaoqing Zhang, <i>Peking University</i> ; Yang Zhang, <i>Beijing Information Science and Technology University</i> ; Duwei Hu, <i>Peking University</i> ; Zhensong Li, <i>Beijing Information Science and Technology University</i> ; Wei Xiang, <i>43rd Institute of China Electronics Technology Group Corporation</i>	
Advancements in Package-on-Package (PoP) Technology, Delivering Performance, Form Factor & Cost Benefits in Next Generation Smartphone Processors	1823
Hamid Eslampour, <i>STATS ChipPAC, Ltd.</i> ; Mukul Joshi, <i>STATS ChipPAC, Ltd.</i> ; SeongWon Park, <i>STATS ChipPAC, Ltd.</i> ; HanGil Shin, <i>STATS ChipPAC, Ltd.</i> ; JaeHan Chung, <i>STATS ChipPAC, Ltd.</i>	
Fabrication of 3D-IC Interposers	1829
John Keech, <i>Corning, Inc.</i> ; Satish Chaparala, <i>Corning, Inc.</i> ; Aric Shorey, <i>Corning, Inc.</i> ; Garrett Piech, <i>Corning, Inc.</i> ; Scott Pollard, <i>Corning, Inc.</i>	

Development of Double-Sided with Double-Chip Stacking Structure Using Panel Level Embedded Wafer Level Packaging	1834
Yen-Fu Su, <i>National Tsing Hua University</i> ; Chun-Te Lin, <i>Industrial Technology Research Institute (ITRI)</i> ; Tzu-Ying Kuo, <i>Industrial Technology Research Institute (ITRI)</i> ; Kuo-Ning Chiang, <i>National Tsing Hua University</i>	
Innovative Ultra Fine Line Ceramic Substrate for Semiconductor Package	1840
Nozomi Shimoishizaka, <i>ConnectTec Japan Corporation</i> ; Takahiro Nakano, <i>ConnectTec Japan Corporation</i> ; Mutsuo Tsuji, <i>ConnectTec Japan Corporation</i> ; Eiji Yamaguchi, <i>ConnectTec Japan Corporation</i> ; Hiroaki Fujimoto, <i>ConnectTec Japan Corporation</i> ; Hirata Katsunori, <i>ConnectTec Japan Corporation</i>	
Development of Ultra-Thin Low Warpage Coreless Substrate	1846
Yu Sun, <i>Chinese Academy of Science</i> ; Xiaofeng He, <i>Chinese Academy of Science</i> ; Zhongyao Yu, <i>Chinese Academy of Science</i> ; Lixi Wan, <i>Chinese Academy of Science</i>	
A Compact ROSA Module for Serial 40-Gb/s Optical Transceiver	1850
Sae-Kyoung Kang, <i>Electronics and Telecommunications Research Institute (ETRI)</i> ; Joon Ki Lee, <i>Electronics and Telecommunications Research Institute (ETRI)</i> ; Joon-Young Huh, <i>Electronics and Telecommunications Research Institute (ETRI)</i> ; Kwangjoon Kim, <i>Electronics and Telecommunications Research Institute (ETRI)</i> ; Jonghyun Lee, <i>Electronics and Telecommunications Research Institute (ETRI)</i>	
Fanout Flipchip eWLB (Embedded Wafer Level Ball Grid Array) Technology as 2.5D Packaging Solutions	1855
Seung Wook Yoon, <i>STATS ChipPAC, Ltd.</i> ; Patrick Tang, <i>STATS ChipPAC, Inc.</i> ; Roger Emigh, <i>STATS ChipPAC, Inc.</i> ; Yaojian Lin, <i>STATS ChipPAC, Ltd.</i> ; Pandi C. Marimuthu, <i>STATS ChipPAC, Ltd.</i> ; Raj Pendse, <i>STATS ChipPAC, Inc.</i>	
Novel Design and Reliability Assessment of a 3D DRAM Stacking Based on Cu-Sn Micro-Bump Bonding and TSV Interconnection Technology	1861
Cao Li, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i> ; Xuefang Wang, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i> ; Mingxiang Chen, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i> ; Shengjun Zhou, <i>Wuhan National Lab for Optoelectronics, Shanghai Jiao Tong University</i> ; Yaping Lv, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i> ; Sheng Liu, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i>	
Assembly Tolerant Design of Multi-Cell Laser Power Converters for Wafer-Level Photonic Packaging	1866
S. Sohr, <i>Technical University Dresden</i> ; R. Rieske, <i>Technical University Dresden</i> ; K. Nieweglowski, <i>Technical University Dresden</i> ; K.-J. Wolter, <i>Technical University Dresden</i>	
Reflection-Phase Variation of Cavity-Resonator-Integrated Guided-Mode-Resonance Reflector for Guided-Mode-Exciting Surface Laser Mirror	1874
Shogo Ura, <i>Kyoto Institute of Technology</i> ; Kenji Kintaka, <i>AIST</i> ; Junichi Inoue, <i>Kyoto Institute of Technology</i> ; Tomonori Ogura, <i>Kyoto Institute of Technology</i> ; Kenzo Nishio, <i>Kyoto Institute of Technology</i> ; Yasuhiro Awatsuji, <i>Kyoto Institute of Technology</i>	
Process Integration of Backside Illuminated Image Sensor with Thin Wafer Handling Technology	1880
H.H. Chang, <i>Industrial Technology Research Institute (ITRI)</i> ; C.H. Chien, <i>Industrial Technology Research Institute (ITRI)</i> ; H.C. Fu, <i>Industrial Technology Research Institute (ITRI)</i> ; W.L. Tsai, <i>Industrial Technology Research Institute (ITRI)</i> ; C.W. Chiang, <i>Industrial Technology Research Institute (ITRI)</i> ; C.T. Ko, <i>Industrial Technology Research Institute (ITRI)</i> ; Y.H. Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; W.C. Lo, <i>Industrial Technology Research Institute (ITRI)</i> ; K.C. Su, <i>Brewer Science</i> ; C.S. Li, <i>Brewer Science</i>	
mmW Characterization of Wafer Level Passivation for 3D Silicon Interposer	1887
Y. Lamy, <i>CEA-LETI</i> ; O. El Bouayadi, <i>CEA-LETI</i> ; C. Ferrandon, <i>CEA-LETI</i> ; A. Schreiner, <i>CEA-LETI</i> ; T. Lacrevez, <i>IMEP-LAHC</i> ; C. Bermond, <i>IMEP-LAHC</i> ; A. Jouve, <i>CEA-LETI</i> ; S. Joblot, <i>STMicroelectronics</i> ; L. Dussopt, <i>CEA-LETI</i> ; B. Fléchet, <i>IMEP-LAHC</i>	

Impact of Wafer Thinning on High-k Metal Gate 20nm Devices	1892
Adam Beece, <i>Rensselaer Polytechnic Institute, GlobalFoundries</i> ; Rahul Agarwal, <i>GlobalFoundries</i> ; Sandhya Chandrashekar, <i>Suss MicroTec</i> ; Jagar Singh, <i>GlobalFoundries</i> ; Siddhartha Siddhartha, <i>GlobalFoundries</i> ; Ramakanth Alapati, <i>GlobalFoundries</i> ; Biju Parameshwaran, <i>Suss MicroTec</i> ; Jeff Dumas, <i>Disco Hi-Tec America, Inc.</i> ; Tyson Alvanos, <i>Disco Hi-Tec America, Inc.</i>	
Design and Optimization of Planar Multimode Waveguides for High Speed, Board-Level Optical Interconnects	1898
Krzysztof Nieweglowski, <i>Technical University Dresden</i> ; Ralf Rieske, <i>Technical University Dresden</i> ; Sebastian Sohr, <i>Technical University Dresden</i> ; Klaus-Juergen Wolter, <i>Technical University Dresden</i>	
Electronic-Microfluidic System for Sorting Particles and Whole Blood Using Gel Electrodes	1905
Jason Luo, <i>University of California, Irvine</i> ; Edward Nelson, <i>University of California, Irvine</i> ; G.-P. Li, <i>University of California, Irvine</i> ; Mark Bachman, <i>University of California, Irvine</i>	
Wafer-Level Integration of Micro-Lens for THz Focal Plane Array Application	1912
Kyoung Youl Park, <i>Michigan State University</i> ; Nophadon Wiwatcharagoses, <i>Michigan State University</i> ; Premjeet Chahal, <i>Michigan State University</i>	
Advanced LED Package with Temperature Sensors and Microfluidic Cooling	1920
H. Ye, <i>Materials Innovation Institute (M2i), Delft University of Technology, Netherlands Organization for Applied Scientific Research (TNO)</i> ; H. van Zeijl, <i>Delft University of Technology</i> ; R. Sokolovskij, <i>Delft University of Technology</i> ; A.W.J. Gielen, <i>Netherlands Organization for Applied Scientific Research (TNO)</i> ; G.Q. Zhang, <i>Delft University of Technology</i>	
Micromachined Wearable/Foldable Super Wideband (SWA) Monopole Antenna Based on a Flexible Liquid Crystal Polymer (LCP) Substrate toward Imaging/Sensing/Health Monitoring Systems	1926
Cheolbok Kim, <i>University of Florida</i> ; Jong Kyu Kim, <i>Electronics and Telecommunications Research Institute (ETRI)</i> ; Kyoung Tae Kim, <i>University of Florida</i> ; Yong-Kyu Yoon, <i>University of Florida</i>	
Three Dimensional Interconnect Using Au and Pillar Bumps	1933
Fei-Jain Wu, <i>Chipbond Technology Corporation</i> ; Lung-Hua Ho, <i>Chipbond Technology Corporation</i> ; Chih-Ming Kuo, <i>Chipbond Technology Corporation</i> ; Chia-Jung Tu, <i>Chipbond Technology Corporation</i> ; Chin-Tang Hsieh, <i>Chipbond Technology Corporation</i> ; Chih-Hsien Ni, <i>Chipbond Technology Corporation</i> ; Shih-Chieh Chang, <i>Chipbond Technology Corporation</i> ; Chuan-Yu Wu, <i>Chipbond Technology Corporation</i> ; Hui-Yu Huang, <i>Chipbond Technology Corporation</i> ; Kung-An Lin, <i>Chipbond Technology Corporation</i> ; You-Ming Hsu, <i>Chipbond Technology Corporation</i>	
Defect Analysis Using High Throughput Plasma FIB in Packaging Reliability Investigations	1940
F. Altmann, <i>Fraunhofer IWM</i> ; S. Klengel, <i>Fraunhofer IWM</i> ; J. Schischka, <i>Fraunhofer IWM</i> ; M. Petzold, <i>Fraunhofer IWM</i>	
High Frequency DC-DC Converter with Co-Packaged Planar Inductor and Power IC	1946
Ningning Wang, <i>University College Cork</i> ; John Barry, <i>University College Cork</i> ; Jason Hannon, <i>University College Cork</i> ; Santosh Kulkarni, <i>University College Cork</i> ; Ray Foley, <i>United Technologies Research Centre</i> ; Kevin McCarthy, <i>University College Cork</i> ; Kenneth Rodgers, <i>University College Cork</i> ; Finbarr Waldron, <i>University College Cork</i> ; Mark Barry, <i>Tyndall National Institute</i> ; Declan Casey, <i>University College Cork</i> ; James Rohan, <i>University College Cork</i> ; Joe O'Brian, <i>University College Cork</i> ; Margaret Hegarty, <i>University College Cork</i> ; Ann-Marie Kelleher, <i>University College Cork</i> ; Saibal Roy, <i>University College Cork</i> ; Cian Ó Mathúna, <i>University College Cork</i>	
Kinetics Study of Intermetallic Growth and its Reliability Implications in Pb-Free, Sn-Based Microbumps in 3D Integration	1953
Yiwei Wang, <i>University of Texas, Austin</i> ; Seung-Hyun Chae, <i>Texas Instruments, Inc.</i> ; Jay Im, <i>University of Texas, Austin</i> ; Paul S. Ho, <i>University of Texas, Austin</i>	

Laminates for Miniaturized Integrated Bioelectronic Protein Analysis Systems	1959
Sara Saedina, <i>University of California, Irvine</i> ; Kevin Limtao, <i>University of California, Irvine</i> ; Kent Nastiuk, <i>University of Rochester Medical Center</i> ; John Krolewski, <i>University of Rochester Medical Center</i> ; G.P. Li, <i>University of California, Irvine</i> ; Mark Bachman, <i>University of California, Irvine</i>	
A New 2.5D TSV Package Assembly Approach	1965
Yuan Lu, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Wen Yin, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Bo Zhang, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Daquan Yu, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Lixi Wan, <i>Chinese Academy of Sciences</i> ; Dongkai Shanguan, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Guofeng Xia, <i>Beijing University of Technology</i> ; Fei Qin, <i>Beijing University of Technology</i> ; Mao Ru, <i>Fudan University</i> ; Fei Xiao, <i>Fudan University</i>	
Fabrication and Characterization of Novel Photodefined Polymer-Enhanced Through-Silicon Vias for Silicon Interposers	1970
Paragkumar A. Thadesar, <i>Georgia Institute of Technology</i> ; Muhannad S. Bakir, <i>Georgia Institute of Technology</i>	
Process Characteristics of a 2.5D Silicon Module Using Embedded Technology as a Feasible Solution for System Integration and Thinner Form-Factor	1975
Ren-Shin Cheng, <i>Industrial Technology Research Institute (ITRI)</i> ; Yin-Po Hung, <i>Industrial Technology Research Institute (ITRI)</i> ; Tzu-Ying Kuo, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Min Lin, <i>Industrial Technology Research Institute (ITRI)</i> ; Fan-Jun Leu, <i>Industrial Technology Research Institute (ITRI)</i> ; Tao-Chih Chang, <i>Industrial Technology Research Institute (ITRI)</i>	
39: Interactive Presentations 3	
Chairs:	Ibrahim Guven, <i>University of Arizona</i> Mark Poliks, <i>Endicott Interconnect Technologies, Inc.</i>
A Lumped/Discrete Port De-Embedding Method by Port Connection Error-Cancelling Network in Full-Wave Electromagnetic Modeling of 3D Integration and Packaging with Vertical Interconnects	1980
Zhaoqing Chen, <i>IBM Corporation</i>	
Current Density Effects on the Electrical Reliability of Ultra Fine-Pitch Micro-Bump for TSV Integration	1988
Young-Bae Park, <i>Andong National University</i> ; Seung-Hyun Kim, <i>Andong National University</i> ; Jong-Jin Park, <i>Andong National University</i> ; June-Bum Kim, <i>Andong National University</i> ; Ho-Young Son, <i>SK Hynix Inc.</i> ; Kwon-Whan Han, <i>SK Hynix Inc.</i> ; Jae-Sung Oh, <i>SK Hynix Inc.</i> ; Nam-Seog Kim, <i>SK Hynix Inc.</i> ; Sehoon Yoo, <i>Korean Institute of Industrial Technology</i>	
Fixture-Free Measurement Technique for PDN Discrete Components	1994
Di Hu, <i>Qualcomm Technologies, Inc.</i> ; Jaemin Shin, <i>Qualcomm Technologies, Inc.</i> ; Timothy Michalka, <i>Qualcomm Technologies, Inc.</i>	
High-Performance RF Components Using Capacitively-Coupled Contacts over III-N Heterostructures	2002
F. Jahan, <i>University of South Carolina</i> ; Y.-H. Yang, <i>University of South Carolina</i> ; M. Gaevski, <i>Sensor Electronic Technology, Inc.</i> ; J. Deng, <i>Sensor Electronic Technology, Inc.</i> ; R. Gaska, <i>Sensor Electronic Technology, Inc.</i> ; M. Shur, <i>Rensselaer Polytechnic Institute</i> ; G. Simin, <i>University of South Carolina</i>	
High-Frequency (RF) Electrical Analysis of Through Silicon Via (TSV) for Different Designed TSV Patterns	2006
Hsin-Kai Huang, <i>Siliconware Precision Industries Co., Ltd.</i> ; Chun-Hsun Lin, <i>Siliconware Precision Industries Co., Ltd.</i> ; Chris Liu, <i>Siliconware Precision Industries Co., Ltd.</i> ; Kwan-Chin Fan, <i>Siliconware Precision Industries Co., Ltd.</i> ; Hsin-Hung Lee, <i>Siliconware Precision Industries Co., Ltd.</i>	

Fast Signal Integrity Methodology for PCB Pre-Layout Analysis and Layout Quality Check	2012
Jimmy Hsu, <i>Intel Corporation</i> ; Thonas Su, <i>Intel Corporation</i> ; Yuan-Liang Li, <i>Intel Corporation</i> ; Edward Hsiung, <i>Intel Corporation</i> ; Kai Xiao, <i>Intel Corporation</i> ; Xiaoning Ye, <i>Intel Corporation</i> ; Kai-Bin Wu, <i>Intel Corporation</i>	
3D Antenna for GHz Application and Vibration Energy Harvesting	2018
Konstantin Kholostov, <i>University of Rome</i> ; Paolo Nenzi, <i>University of Rome</i> ; Fabrizio Palma, <i>University of Rome</i> ; Marco Balucani, <i>University of Rome</i>	
Electrical Performance Modeling of Unbalanced Comb Tree Networks on Advanced PCB Interconnects for High-Rate Clock Signal Distribution	2024
Thomas Eudes, <i>ESIGELEC</i> ; Blaise Ravelo, <i>ESIGELEC</i> ; Thierry Lacrevez, <i>Université de Savoie</i> ; Bernard Fléchet, <i>Université de Savoie</i>	
Far-End Crosstalk Cancellation Using Via Stub for DDR4 Memory Channel	2035
Chien-Ming Nieh, <i>University of Florida</i> ; Jongbae Park, <i>Intel Corporation</i>	
Practical Investigations of Fiber Weave Effects on High-Speed Interfaces	2041
Gerardo Romo Luevano, <i>Qualcomm Technologies, Inc.</i> ; Jaemin Shin, <i>Qualcomm Technologies, Inc.</i> ; Timothy Michalka, <i>Qualcomm Technologies, Inc.</i>	
High-Speed Packages with Imperfect Power and Ground Planes	2046
Kai Liu, <i>STATS ChipPAC, Inc.</i> ; Robert Frye, <i>RF Design Consulting, LLC</i> ; MaPhooPwint Hlaing, <i>STATS ChipPAC, Ltd.</i> ; YongTaek Lee, <i>STATS ChipPAC, Ltd.</i> ; HyunTai Kim, <i>STATS ChipPAC, Ltd.</i> ; Gwang Kim, <i>STATS ChipPAC, Ltd.</i> ; Susan Park, <i>STATS ChipPAC, Ltd.</i> ; Billy Ahn, <i>STATS ChipPAC, Ltd.</i>	
A Miniaturized Module for Bluetooth/GPS by Embedding Capacitors in Printed-Circuit- Board and Using Interposer	2052
Jong-In Ryu, <i>Korea Electronics Technology Institute</i> ; Se-Hoon Park, <i>Korea Electronics Technology Institute</i> ; Dongsu Kim, <i>Korea Electronics Technology Institute</i> ; Jun-Chul Kim, <i>Korea Electronics Technology Institute</i> ; Jong-Chul Park, <i>Korea Electronics Technology Institute</i>	
Optimal Common-Mode Choke Selection for the High Definition Video Interface for the Mobile Application	2058
Junwoo Lee, <i>Silicon Image, Inc.</i> ; Youchul Jeong, <i>Silicon Image, Inc.</i> ; Baegin Sung, <i>Silicon Image, Inc.</i>	
DC Wander Effect of DC Blocking Capacitors on PCIe Gen3 Signal Integrity	2063
Nanju Na, <i>IBM Systems and Technology Group</i> ; Daniel M. Dreps, <i>IBM Systems and Technology Group</i> ; Jose A. Hejase, <i>IBM Systems and Technology Group</i>	
Pre-Emphasis Parameter Optimization for High Speed Channels Using De-Convolution Approach	2069
Jifeng Mao, <i>Dell Force10</i> ; Umesh Chandra, <i>Dell Force10</i>	
Graphene Heat Spreader for Thermal Management of Hot Spots	2075
Zhaoli Gao, <i>Chalmers University of Technology, Hong Kong University of Science and Technology</i> ; Yong Zhang, <i>Chalmers University of Technology, Shanghai University</i> ; Yifeng Fu, <i>SHT Smart High Tech AB</i> ; Matthew Yuen, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Johan Liu, <i>Chalmers University of Technology, Shanghai University</i>	
Modeling and Simulation of Low Duty Ratio Buck Synchronous Converter under Large Load Current Switching	2079
Jai P. Agrawal, <i>Purdue University</i>	
Compact TSV-Based Wideband Bandpass Filters on 3-D IC	2083
Ying-Cheng Tseng, <i>National Taiwan University</i> ; Peng-Shu Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; Wei-Chung Lo, <i>Industrial Technology Research Institute (ITRI)</i> ; Shih-Hsien Wu, <i>Industrial Technology Research Institute (ITRI)</i> ; Tzong-Lin Wu, <i>National Taiwan University</i>	

Implementation of a MIMO Antenna Design for USB Dongle Applications	2089
Yu-Kai Tseng, <i>National Sun Yat-Sen University</i> ; Yi-Chieh Lin, <i>National Sun Yat-Sen University</i> ; Lih-Tyng Hwang, <i>National Sun Yat-Sen University</i>	
Efficient Complex Broadside Coupled Trace Modeling and Estimation of Crosstalk Impact Using Statistical BER Analysis for High Volume, High Performance Printed Circuit Board Designs	2095
Arun Reddy Chada, <i>Missouri S&T EMC Laboratory</i> ; Songping Wu, <i>Missouri S&T EMC Laboratory</i> ; Jun Fan, <i>Missouri S&T EMC Laboratory</i> ; James L. Drewniak, <i>Missouri S&T EMC Laboratory</i> ; Bhyrav Mutnury, <i>Dell, Inc.</i> ; Daniel N. de Araujo, <i>Nimbic</i>	
Terahertz Micropolarizers Using Carbon Microfibers	2102
Amanpreet Kaur, <i>Michigan State University</i> ; Kyoung Youl Park, <i>Michigan State University</i> ; Xianbo Yang, <i>Michigan State University</i> ; Nophadon Wiwatcharagoses, <i>Michigan State University</i> ; Premjeet Chahal, <i>Michigan State University</i>	
Layout Parameter Optimization Based Power and Signal Integrity Performance Improvement of High-Speed Interfaces of Wirebond Packages	2107
Om P. Mandhana, <i>Intel Corporation</i> ; Jin Zhao, <i>Intel Corporation</i>	
3D IC-Package-Board Co-Analysis Using 3D EM Simulation for Mobile Applications	2113
Darryl Kostka, <i>CST of America</i> ; Taigon Song, <i>Georgia Institute of Technology</i> ; Sung Kyu Lim, <i>Georgia Institute of Technology</i>	
3D eWLB – Horizontal and Vertical Interconnects for Integration of Passive Components	2121
M. Wojnowski, <i>Infineon Technologies AG</i> ; G. Sommer, <i>Infineon Technologies AG</i> ; K. Pressel, <i>Infineon Technologies AG</i> ; G. Beer, <i>Infineon Technologies AG</i>	
40: Interactive Presentations 4	
Chairs:	Patrick Thompson, <i>Texas Instruments, Inc.</i> Rao Bonda, <i>Amkor Technology</i>
Piezoresistive Stress Sensor for Inline Monitoring During Assembly and Packaging of QFN	2126
Thomas Schreier-Alt, <i>Fraunhofer IZM</i> ; Gerhard Chmiel, <i>Elmos Semiconductor AG</i> ; Frank Ansoerge, <i>Fraunhofer IZM</i> ; Klaus-Dieter Lang, <i>Technical University Berlin</i>	
Thermo-Mechanical Reliability of Copper-Filled and Polymer-Filled Through Silicon Vias in 3D Interconnects	2132
Xiang Gao, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i> ; Run Chen, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i> ; Xuefang Wang, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i> ; Xiaobing Luo, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i> ; Sheng Liu, <i>Huazhong University of Science & Technology, Wuhan National Lab for Optoelectronics</i>	
Electrochemical Reactions in Solder Mask of Flip Chip-Plastic Ball Grid Array Package	2138
Kang-Wook Lee, <i>IBM T.J. Watson Research Center</i> ; Stephane Barbeau, <i>IBM Strategy and Transformation</i> ; Francois Racicot, <i>IBM Strategy and Transformation</i> ; Douglas Powell, <i>IBM Strategy and Transformation</i> ; Charles Arvin, <i>IBM Strategy and Transformation</i> ; Thomas Wassick, <i>IBM Strategy and Transformation</i> ; Joseph Ross, <i>IBM Strategy and Transformation</i>	
Design and Assembly Process Simulation for an Automotive Power Module	2144
Yong Liu, <i>Fairchild Semiconductor Corporation</i> ; Qiuxiao Qian, <i>Fairchild Semiconductor Corporation</i> ; Byoungok Lee, <i>Fairchild Semiconductor Corporation</i> ; Taekkeun Lee, <i>Fairchild Semiconductor Corporation</i> ; Joonseo Son, <i>Fairchild Semiconductor Corporation</i> ; Oseob Jeon, <i>Fairchild Semiconductor Corporation</i>	
Investigation of Copper-Tin Transient Liquid Phase Bonding Reliability for 3D Integration	2151
A. Garnier, <i>CEA-LETI</i> ; C. Grémion, <i>CEA-LETI</i> ; R. Franiatte, <i>CEA-LETI</i> ; D. Bouchu, <i>CEA-LETI</i> ; R. Anciant, <i>CEA-LETI</i> ; S. Chéramy, <i>CEA-LETI</i>	

Development of PCB Design Guide and PCB Deformation Simulation Tool for Slim PCB Quality and Reliability	2157
<i>Soonwan Chung, Samsung Electronics Company, Ltd.; Gyun Heo, Samsung Electronics Company, Ltd.; Jae Kwak, Samsung Electronics Company, Ltd.; Seunghee Oh, Samsung Electronics Company, Ltd.; Yongwon Lee, Samsung Electronics Company, Ltd.; Changsun Kang, Samsung Electronics Company, Ltd.; Tackmo Lee, Samsung Electronics Company, Ltd.</i>	
Thermal Cycling Effect on Intermetallic Formation with Various Surface Finish of Micro Bump Interconnect for 3D Package	2163
<i>Mu-Hsuan Chan, Siliconware Precision Industries Co., Ltd.; Yi-Chian Liao, Siliconware Precision Industries Co., Ltd.; Chun-Tang Lin, Siliconware Precision Industries Co., Ltd.; Kuan-Weir Chuang, Siliconware Precision Industries Co., Ltd.; Huei-Nuan Huang, Siliconware Precision Industries Co., Ltd.; Chi-Tung Yeh, Siliconware Precision Industries Co., Ltd.; Wen-Tsung Tseng, Siliconware Precision Industries Co., Ltd.; Jeng-Yuan Lai, Siliconware Precision Industries Co., Ltd.</i>	
Development of 300 mm TSV Interposer with Redistribution Layers on Both Sides Using MEMS Processes	2168
<i>Seichi Yoshimi, Dai Nippon Printing Co., Ltd., NMEMS Technology Research Organization; Koji Fujimoto, Dai Nippon Printing Co., Ltd., NMEMS Technology Research Organization; Miyuki Akazawa, Dai Nippon Printing Co., Ltd., NMEMS Technology Research Organization; Hidenobu Matsumoto, Dai Nippon Printing Co., Ltd.; Hiroshi Mawatari, Dai Nippon Printing Co., Ltd.; Kousuke Suzuki, Dai Nippon Printing Co., Ltd.; Toshihiro Itoh, NMEMS Technology Research Organization, Advanced Industrial Science and Technology; Ryutarō Maeda, NMEMS Technology Research Organization, Advanced Industrial Science and Technology</i>	
Optical Transceiver Sub-System Package based on SiOB with 8×14Gbps Two-Way Bandwidth	2173
<i>Fengman Liu, Institute of Microelectronics of Chinese Academy of Sciences; Binbin Yang, Institute of Microelectronics of Chinese Academy of Sciences; Baoxia Li, Institute of Microelectronics of Chinese Academy of Sciences; Haidong Wang, Institute of Microelectronics of Chinese Academy of Sciences; Lixi Wan, Institute of Microelectronics of Chinese Academy of Sciences</i>	
Understanding Loss Mechanisms of Passive Interconnects with Innovative/Cost Effective Structure Implementations for Supporting 28Gbps and Beyond Transmission	2179
<i>Namhoon Kim, Xilinx, Inc.; Joong-Ho Kim, Xilinx, Inc.; Ray Anderson, Xilinx, Inc.; Paul Wu, Xilinx, Inc.; Suresh Ramalingam, Xilinx, Inc.</i>	
Numerical Comparison of the Thermal Performance of 3D Stacking and Si Interposer Based Packaging Concepts	2183
<i>H. Oprins, IMEC; B. Vandevelde, IMEC; M. Badaroglu, IMEC; M. Gonzalez, IMEC; G. Van der Plas, IMEC; E. Beyne, IMEC</i>	
Investigation of Modern Electrically Conductive Adhesives for Die-Attachment in Power Electronics Applications	2189
<i>Johanna Ocklenburg, University of Freiburg; Eugen Rastjagaev, Infineon Technologies Austria AG; Juergen Wilde, University of Freiburg</i>	
Shape Engineering of the Fillers in Stretchable, Electrically Conductive Adhesives: Its Effect on Percolation and Conductivity Change During Stretching	2196
<i>Zhuo Li, Georgia Institute of Technology; Kristen Hansen, Georgia Institute of Technology; Kyoung-Sik Moon, Georgia Institute of Technology; C.P. Wong, Georgia Institute of Technology, Chinese University of Hong Kong</i>	
Electrochemically Etched TSV for Porous Silicon Interposer Technologies	2201
<i>Paolo Nenzi, University of Rome; Konstantin Kholostov, University of Rome; Rocco Crescenzi, University of Rome; Hanna Bondarenka, BSUIR; Vitaly Bondarenko, BSUIR; Marco Balucani, University of Rome</i>	

Role of FBEOL AI Pads and Hard Dielectric for Improved Mechanical Performance in Lead-Free C4 Products	2208
<i>E. Misra, IBM Microelectronics Division; T. Daubenspeck, IBM Microelectronics Division; T. Wassick, IBM Microelectronics Division; K. Tunga, IBM Microelectronics Division; D. Questad, IBM Microelectronics Division; G. Osborne, IBM Microelectronics Division; T.M. Shaw, IBM Microelectronics Division; K. McLaughlin, IBM Microelectronics Division</i>	
Modeling and Simulation of the Comb Structure in the Presence of Imperfections	2214
<i>Zhang Luo, Huazhong University of Science & Technology, Wuhan National Laboratory for Optoelectronics; Sheng Liu, Huazhong University of Science & Technology, Wuhan National Laboratory for Optoelectronics; Gang Cao, Huazhong University of Science & Technology, Wuhan National Laboratory for Optoelectronics; Xiaojie Chen, Huazhong University of Science & Technology, Wuhan National Laboratory for Optoelectronics</i>	
Realization of Ultra-Low Power I/O	2218
<i>Lei Shan, IBM T.J. Watson Research Center; Timothy Dickson, IBM T.J. Watson Research Center; Young Kwark, IBM T.J. Watson Research Center; Christian Baks, IBM T.J. Watson Research Center; Dale Becker, IBM T.J. Watson Research Center; Roger Krabbenhoft, IBM T.J. Watson Research Center; Timothy Chainer, IBM T.J. Watson Research Center; Sebastian Mueller, Technical University of Hamburg; Manabu Hoshino, Zeon Corporation; Junji Kodemura, Zeon Corporation; Masakazu Hashimoto, Zeon Corporation; Toshihiko Jimbo, Zeon Chemicals; Christopher Blatt, Zeon Chemicals</i>	
Assembly Level Digital Image Correlation under Reflow and Thermal Cycling Conditions	2223
<i>W.C. Ralph, Southern Research Institute; G.F. Raiser, Medtronic, Inc.</i>	
Thermo-Mechanical Simulations of a Copper-to-Copper Direct Bonded 3D TSV Chip Package Interaction Test Vehicle	2228
<i>Ah-Young Park, State University of New York, Binghamton; Daniel Ferrone, State University of New York, Binghamton; Stephen Cain, State University of New York, Binghamton; Dae Young Jung, State University of New York, Binghamton; Bruce T. Murray, State University of New York, Binghamton; Seungbae Park, State University of New York, Binghamton; Klaus Hummler, SEMATECH</i>	
Characterization and Modeling of Copper TSVs for Silicon Interposers	2235
<i>D. Malta, RTI International; C. Gregory, RTI International; M. Lueck, RTI International; J. Lannon, RTI International; J. Lewis, RTI International; D. Temple, RTI International; P. DiFonzo, U.S. Department of Defense; F. Naumann, Fraunhofer IWM; M. Petzold, Fraunhofer IWM</i>	
Design, Fabrication and Assembly of a Novel Electrical and Microfluidic I/Os for 3-D Chip Stack and Silicon Interposer	2243
<i>Li Zheng, Georgia Institute of Technology; Yue Zhang, Georgia Institute of Technology; Muhannad S. Bakir, Georgia Institute of Technology</i>	
Homogenization of TSV Interposer and Quick Assessment of its Thermomechanical Influence on 3D Packages	2249
<i>Cheng Fu Chen, University of Alaska, Fairbanks</i>	
Post Assembly Warpage Prediction Using Refined Zigzag Element	2255
<i>Bahattin Kilic, Intel Corporation; Atila Barut, University of Arizona; Erdogan Madenci, University of Arizona</i>	
Atomistic Study of Welding of Carbon Nanotubes onto Metallic Substrates	2259
<i>Xiaohui Song, Wuhan National Lab for Optoelectronics, Henan Academy of Sciences; Mingxiang Chen, Wuhan National Lab for Optoelectronics; Zhinyin Gan, Wuhan National Lab for Optoelectronics</i>	

41: Student Interactive Presentations

Chairs: Mark Poliks, *Endicott Interconnect Technologies*
Mark Eblen, *Kyocera America, Inc.*

- Analyses of Propagation Behavior of Crack at Interface between Die-Attach and Cu Base and Cracks' Effects on Reliability of High Brightness Light-Emitting Diode (LED)** 2264
Xiang Gao, *Huazhong University of Science & Technology, Wuhan National Laboratory for Optoelectronics*; Xin Wu, *Wayne State University*; Yong Xu, *Wayne State University*; Sheng Liu, *Huazhong University of Science & Technology, Wuhan National Laboratory for Optoelectronics*
- Packaging and Sensing Platform Using Opto-Electronic Zinc Oxide Nano-Heterostructure Integration** 2271
Anurag Gupta, *University of Alabama*; Mitchell Spryn, *University of Alabama*; Bruce Kim, *University of Alabama*; Eugene Edwards, *U.S. Army, RDECOM/AMRDEC*; Christina Brantley, *U.S. Army, RDECOM/AMRDEC*; Paul Ruffin, *U.S. Army, RDECOM/AMRDEC*
- Fluxless Tin Bonding of Silicon Chips to Iron** 2276
Shou-Jen Hsu, *University of California, Irvine*; Chin C. Lee, *University of California, Irvine*
- A Small Flat-Plate Vapor Chamber Fabricated by Copper Powder Sintering and Diffusion Bonding for Cooling Electronic Packages** 2280
Run Hu, *Huazhong University of Science & Technology*; Tinghui Guo, *Huazhong University of Science & Technology*; Xiaolei Zhu, *Huazhong University of Science & Technology*; Sheng Liu, *Huazhong University of Science & Technology*; Xiaobing Luo, *Huazhong University of Science & Technology*
- Buffered Distributed Spray MOCVD Reactor for LED Production** 2286
Shaolin Hu, *Huazhong University of Science & Technology, Guangdong RealFaith Semiconductor Equipment Co., Ltd.*; Zhiyin Gan, *Huazhong University of Science & Technology, Guangdong RealFaith Semiconductor Equipment Co., Ltd.*; Sheng Liu, *Huazhong University of Science & Technology*
- Injection Molding of a WDM System for POF Communication** 2292
S. Höll, *Harz University of Applied Studies and Research*; M. Haupt, *Harz University of Applied Studies and Research*; U.H.P. Fischer, *Harz University of Applied Studies and Research*
- TSV Electrical and Mechanical Modeling for Thermo-Mechanical Delamination** 2298
Kaushal Kannan, *University of Alabama*; Suresh Kannan, *University of Alabama*; Bruce Kim, *University of Alabama*; Suresh Sitaraman, *Georgia Institute of Technology*; Susan Burkett, *University of Alabama*
- D-Band Characterization of Co-Planar Wave Guide and Microstrip Transmission Lines on Liquid Crystal Polymer** 2304
Wasif Tanveer Khan, *Georgia Institute of Technology*; A. Çağrı Ulusoy, *Georgia Institute of Technology*; John Papapolymerou, *Georgia Institute of Technology*
- Optimization of Underfill Material for Better Reliability and Thermal Behavior of 3D Packages with TSVs** 2310
Yeonsung Kim, *State University of New York, Binghamton*;
S.B. Park, *State University of New York, Binghamton*
- 3D Modeling of High Count Fine Pitch Flip Chip Assemblies** 2319
W. Kpobie, *Ecole Nationale d'Ingénieurs de Metz (ENIM), CEA-LETI*; N. Bonfoh, *Ecole Nationale d'Ingénieurs de Metz (ENIM)*; C. Dreistadt, *Ecole Nationale d'Ingénieurs de Metz (ENIM)*;
M. Fendler, *CEA-LETI*; P. Lipinski, *Ecole Nationale d'Ingénieurs de Metz (ENIM)*
- High Aspect Ratio Sub-100 nm Silicon Vias (SVs) by Metal-Assisted Chemical Etching (MaCE) and Copper Filling** 2326
Liyi Li, *Georgia Institute of Technology*; C.P. Wong, *Georgia Institute of Technology, Chinese University of Hong Kong*

Stretchable/Printed RF Devices Via High-Throughput, High-Definability, Soft-Lithography Fabrication	2332
<i>Zhuo Li, Georgia Institute of Technology; Liyi Li, Georgia Institute of Technology; Kyoung-Sik Moon, Georgia Institute of Technology; Fan Cai, Georgia Institute of Technology; John Papapolymerou, Georgia Institute of Technology; C.P. Wong, Georgia Institute of Technology, Chinese University of Hong Kong</i>	
Stress Analysis in 3D IC having Thermal Through Silicon Vias (TTSV)	2337
<i>Shabaz Basheer Patel, Indian Institute of Technology Hyderabad; Tamal Ghosh, Indian Institute of Technology Hyderabad; Asudeb Dutta, Indian Institute of Technology Hyderabad; Shivgovind Singh, Indian Institute of Technology Hyderabad</i>	
Electronic Packages for High Pressure Applications: A Dome-Shaped Cavity Design	2342
<i>Eric Jian Rong Phua, Institute of Microelectronics; Riko I Made, Nanyang Technological University; Ahmed Sharif, Nanyang Technological University; Chee Cheong Wong, Nanyang Technological University; Zhong Chen, Nanyang Technological University; Daniel Rhee MinWoo, Nanyang Technological University; Chee Lip Gan, Nanyang Technological University</i>	
3D Chips Can Be Cool: Thermal Study of VeSFET-Based Ics	2349
<i>Xiang Qiu, University of California, Santa Barbara; Malgorzata Marek-Sadowska, University of California, Santa Barbara; Wojciech Maly, Carnegie Mellon University</i>	
Power Dissipation Analysis for Different Configurations of TSVs at High (GHz) Frequencies	2356
<i>Aditya Vikram Singh, Indian Institute of Technology Hyderabad; Divanshu Chaturvedi, Indian Institute of Technology Hyderabad; Shiv Govind Singh, Indian Institute of Technology Hyderabad; Mohammed Zafar Ali Khan, Indian Institute of Technology Hyderabad</i>	
Fabrication of Deep Vias/Grooves as Interconnection Path by Wet Etching for Wafer Level Packaging of GaAs Based Image Sensor	2361
<i>Shuangfu Wang, Chinese Academy of Sciences; Jiaotuo Ye, Chinese Academy of Sciences; Le Luo, Chinese Academy of Sciences</i>	
An Experimental Verified Model for Cu Electrodeposition Simulation for the Filling of High Aspect Ratio Through Silicon Vias	2366
<i>Heng Wu, Dalian University of Technology, Jiangsu R&D Center for Internet of Things; Zhen-an Tang, Dalian University of Technology; Zhu Wang, Chinese Academy of Sciences, National Center for Advanced Packaging; Wan Cheng, Jiangsu R&D Center for Internet of Things, National Center for Advanced Packaging; Chongsheng Song, Chinese Academy of Sciences, National Center for Advanced Packaging; Daquan Yu, Chinese Academy of Sciences, Jiangsu R&D Center for Internet of Things, National Center for Advanced Packaging; Lixi Wan, Chinese Academy of Sciences</i>	
Fabrication of Gel Glass Containing High Rendering Phosphor Mixture Via Sol-Gel Process for LEDs	2371
<i>Liang Yang, Wuhan National Laboratory for Optoelectronics, Huazhong University of Science & Technology; Mingxiang Chen, Huazhong University of Science & Technology; Sheng Liu, Wuhan National Laboratory for Optoelectronics, Huazhong University of Science & Technology</i>	
Implementation of Semiconducting Nanowires for the Design of THz Detectors	2375
<i>Xianbo Yang, Michigan State University; Amanpreet Kaur, Michigan State University; Premjeet Chahal, Michigan State University</i>	
Study of Low Load and Temperature, High Heat-Resistant Solid-Phase Sn-Ag Bonding with Formation of Ag₃Sn Intermetallic Compound Via Nanoscale Thin Film Control for Wafer-Level 3D-Stacking for 3D LSI	2381
<i>Kiyoto Yoneta, Osaka University; Ryohei Sato, Osaka University; Yoshiharu Iwata, Osaka University; Koichiro Atsumi, Osaka University; Kazuya Okamoto, Osaka University; Yukihiko Sato, Osaka University</i>	
A Compact Inductively Coupled Connector for Mobile Devices	2385
<i>Wenxu Zhao, North Carolina State University; Peter Gadfort, North Carolina State University; Evan Erickson, North Carolina State University; Paul D. Franzon, North Carolina State University</i>	